



PROTON-ELECTROTEX RUSSIA

Low switching losses
Low reverse recovery charge
Distributed amplified gate for high di_T/dt

Fast Thyristor TFI353-700-30

Maximum allowable mean on-state current	I_{TAV}	700 A
Repetitive peak off-state voltage	V_{DRM}	3000 V
Repetitive peak reverse voltage	V_{RRM}	
Turn-off time	t_q	40.0, 50.0, 63.0 μs
V_{DRM}, V_{RRM}, V	3000	
Voltage code	30	
$T_j, ^\circ C$	-60...+120	

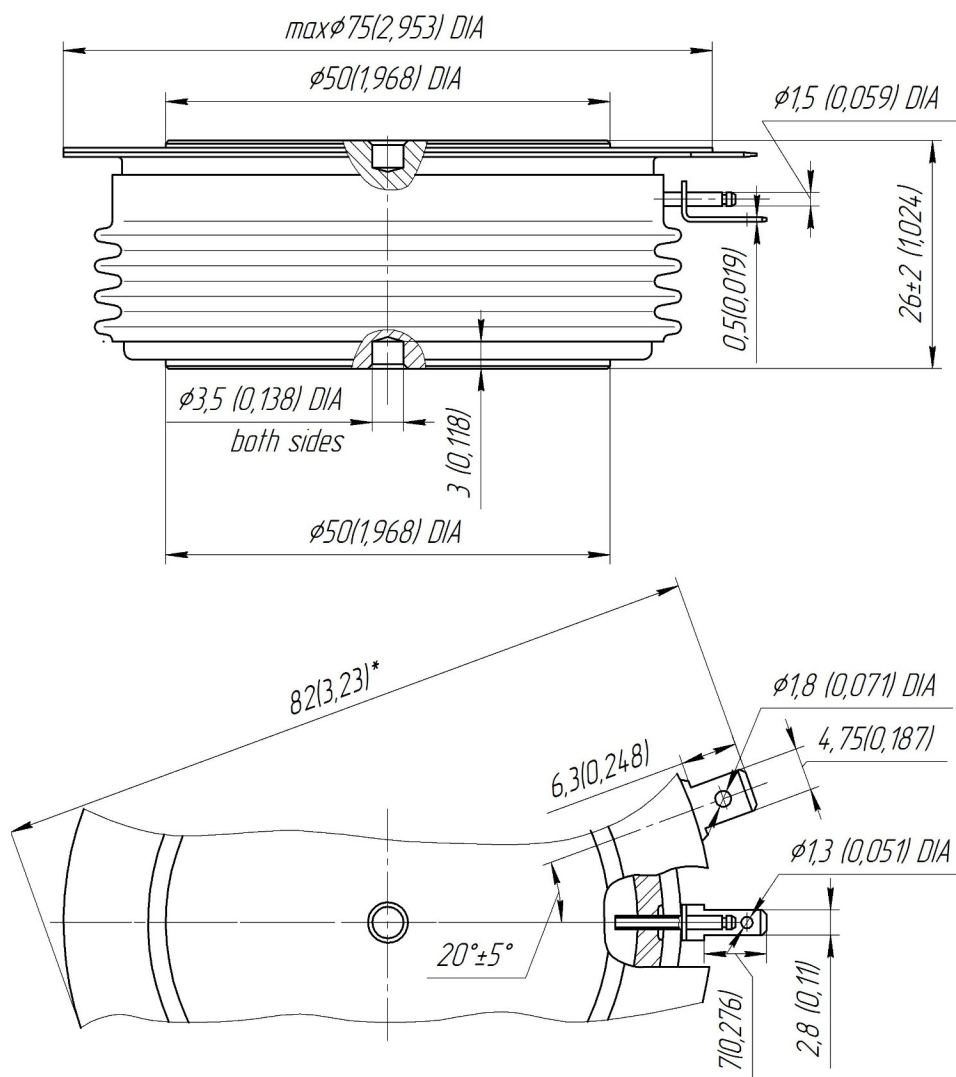
MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Maximum allowable mean on-state current	A	700 1125	T _c =87 °C; Double side cooled; T _c =55 °C; Double side cooled; 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	1100	T _c =87 °C; Double side cooled; 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	14.0 16.0	T _j =T _{j max} T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse:I _G =I _{FGM} ; V _G =20 V; t _{GP} =50 μs; di _G /dt=1 A/μs
			15.0 17.0	T _j =T _{j max} T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse:I _G =I _{FGM} ; V _G =20 V; t _{GP} =50 μs; di _G /dt=1 A/μs
I ² t	Safety factor	A ² s·10 ³	980 1280	T _j =T _{j max} T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse:I _G =I _{FGM} ; V _G =20 V; t _{GP} =50 μs; di _G /dt=1 A/μs
			930 1190	T _j =T _{j max} T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse:I _G =I _{FGM} ; V _G =20 V; t _{GP} =50 μs; di _G /dt=1 A/μs
BLOCKING					
V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	3000	T _{j min} < T _j < T _{j max} ; 180° half-sine wave; 50 Hz; Gate open	
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	3100	T _{j min} < T _j < T _{j max} ; 180° half-sine wave; single pulse; Gate open	
V _D , V _R	Direct off-state and Direct reverse voltages	V	0.6·V _{DRM} 0.6·V _{RRM}	T _j =T _{j max} ; Gate open	

TRIGGERING				
I _{FGM}	Peak forward gate current	A	8	T _j =T _{j max}
V _{RGM}	Peak reverse gate voltage	V	5	
P _G	Gate power dissipation	W	8	T _j =T _{j max} for DC gate current
SWITCHING				
(di _T /dt) _{crit}	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/μs	2000	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; I _{TM} =2 I _{TAV} ; Gate pulse: I _G =2 A; V _G =20 V; t _{GP} =50 μs; di _G /dt=2 A/μs
THERMAL				
T _{stg}	Storage temperature	°C	−60...+50	
T _j	Operating junction temperature	°C	−60...+120	
MECHANICAL				
F	Mounting force	kN	24.0...28.0	
a	Acceleration	m/s ²	50	Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions		
ON-STATE						
V _{TM}	Peak on-state voltage, max	V	3.20 2.85	T _j = T _{j max} ; I _{TM} =3200 A T _j =25 °C; I _{TM} =2512 A		
V _{T(TO)}	On-state threshold voltage, max	V	1.50	T _j =T _{j max} ;		
r _T	On-state slope resistance, max	mΩ	0.500	0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}		
I _H	Holding current, max	mA	500	T _j =25 °C; V _D =12 V; Gate open		
BLOCKING						
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	150	T _j =T _{j max} ; V _D =V _{DRM} ; V _R =V _{RRM}		
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage ¹⁾ , min	V/μs	200, 320, 500, 1000	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; Gate open		
TRIGGERING						
V _{GT}	Gate trigger direct voltage, max	V	4.00 2.50 2.00	T _j = T _{j min} T _j =25 °C T _j = T _{j max}	V _D =12 V; I _D =3 A; Direct gate current	
I _{GT}	Gate trigger direct current, max	mA	500 300 200	T _j = T _{j min} T _j = 25 °C T _j = T _{j max}		
V _{GD}	Gate non-trigger direct voltage, min	V	0.25	T _j =T _{j max} ; V _D =0.67·V _{DRM} ;		
I _{GD}	Gate non-trigger direct current, min	mA	10.00	Direct gate current		
SWITCHING						
t _{gd}	Delay time, max	μs	0.88	T _j =25 °C; V _D =1500 V; I _{TM} =I _{TAV} ; di/dt=200 A/μs;		
t _{gt}	Turn-on time ²⁾	μs	2.50, 3.20, 4.00, 6.30	Gate pulse: I _G =2 A; V _G =20 V; t _{GP} =50 μs; di _G /dt=2 A/μs		
t _q	Turn-off time ³⁾ , max	μs	40.0, 50.0, 63.0	dv _D /dt=50 V/μs;	T _j =T _{j max} ; I _{TM} = I _{TAV} ; di _R /dt=-10 A/μs; V _R =100V; V _D =0.67 V _{DRM}	
			50.0, 63.0, 80.0	dv _D /dt=200 V/μs;		
Q _{rr}	Recovered charge, max	μC	770	T _j =T _{j max} ; I _{TM} =I _{TAV} ;		
t _{rr}	Reverse recovery time, max	μs	7.0	di _R /dt=-50 A/μs;		
I _{rr}	Reverse recovery current, max	A	220	V _R =100 V		



All dimensions in millimeters (inches)

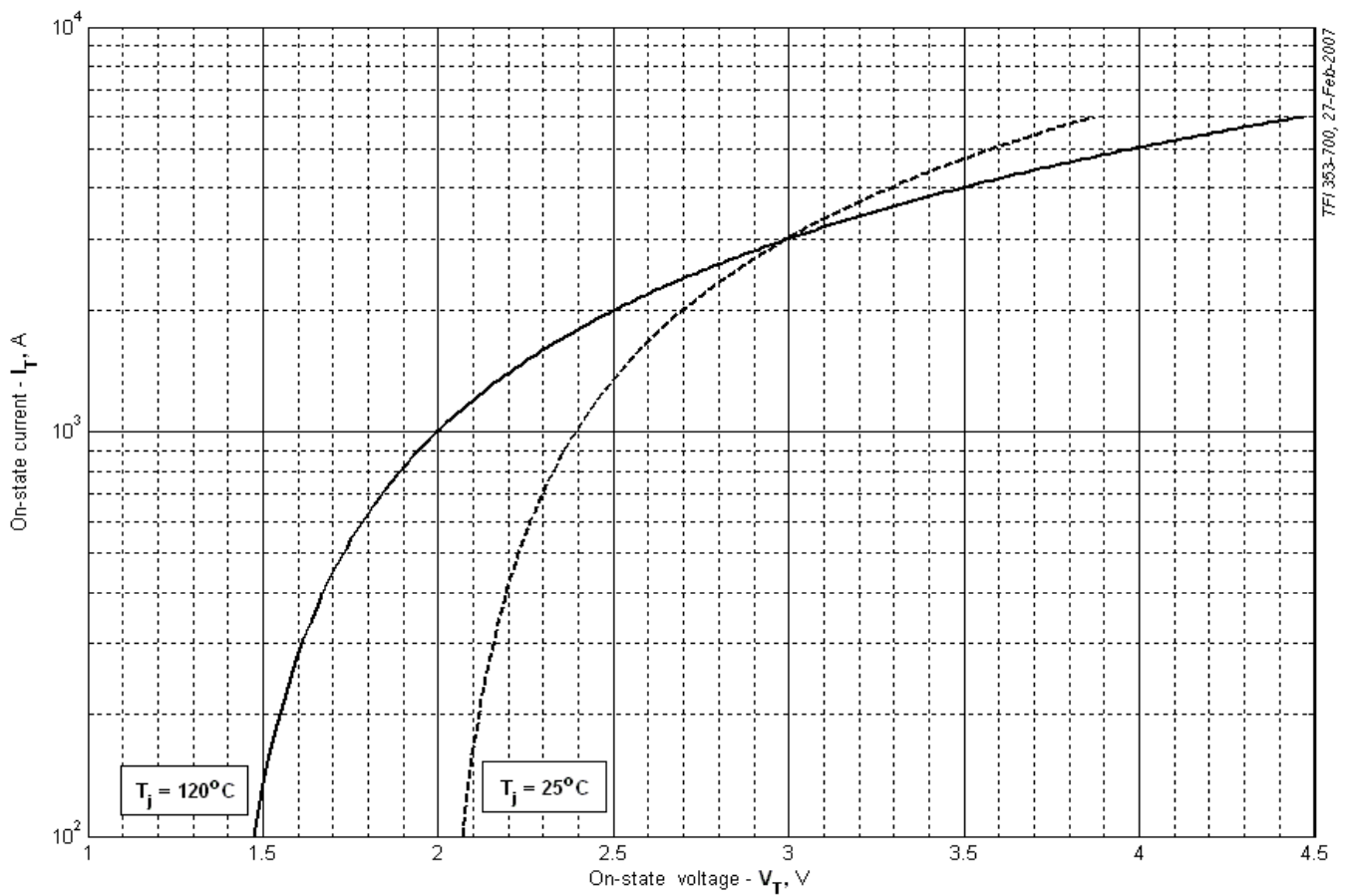


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_J = 25^\circ\text{C}$	$T_J = T_{J\text{max}}$
A	1.967194	1.329742
B	0.254400	0.439131
C	-0.166422	-0.222268
D	0.285964	0.381925

On-state characteristic model (see Fig. 1)

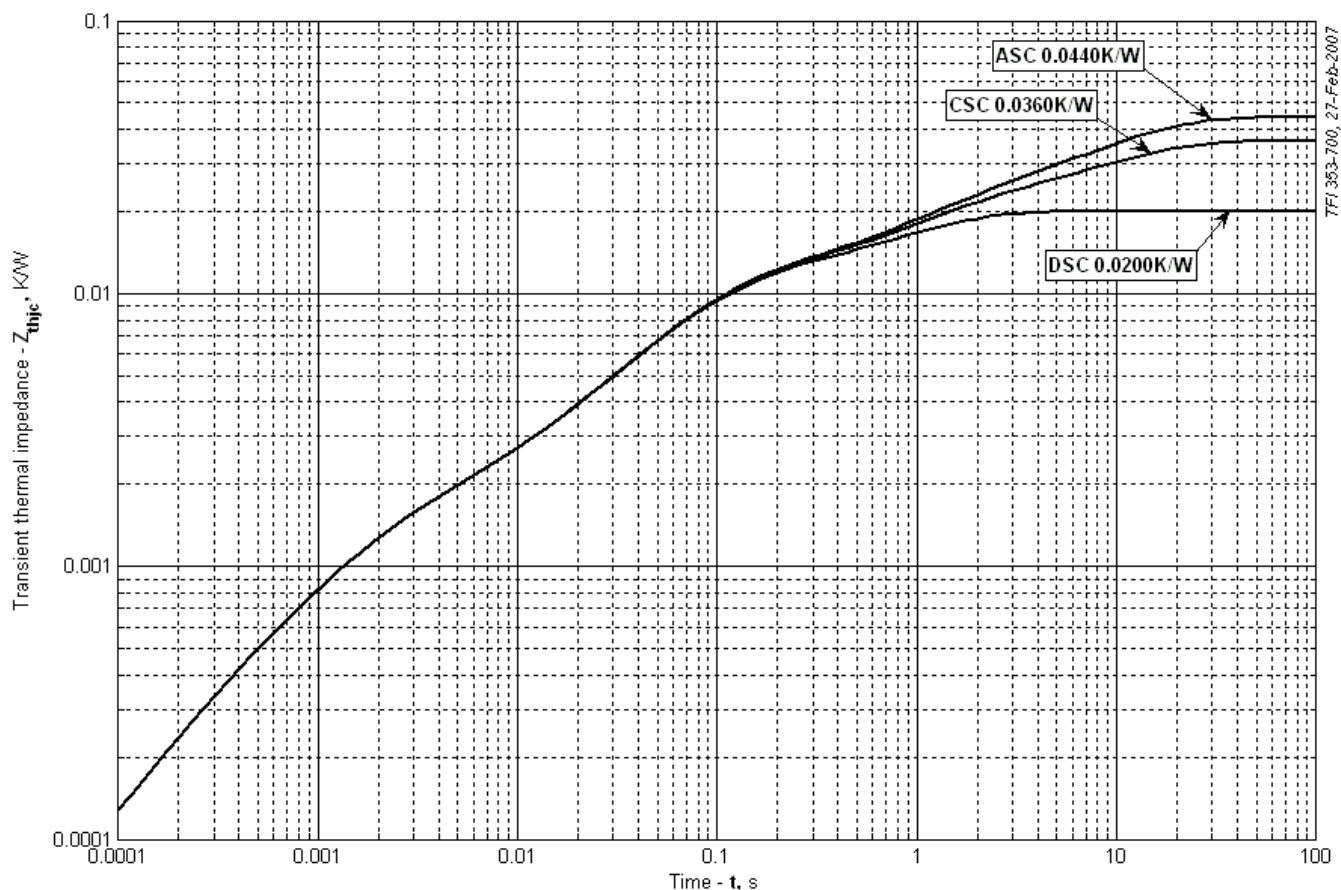


Fig 2 – Transient thermal impedance

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
$R_i, K/W$	-1.888e-006	0.009096	0.009331	0.0001969	0.001089	0.000289
τ_i, s	9.752	0.9752	0.06926	0.02587	0.00197	0.0004773

DC Cathode side cooled

i	1	2	3	4	5	6
$R_i, K/W$	0.01613	0.008994	0.00918	0.0004987	0.001111	0.0002592
τ_i, s	9.752	1.077	0.06877	0.2401	0.001906	0.0004449

DC Anode side cooled

i	1	2	3	4	5	6
$R_i, K/W$	0.02418	0.009264	0.00939	3.212e-007	0.001074	0.0003088
τ_i, s	9.752	1.078	0.07024	0.2399	0.00201	0.0005003

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

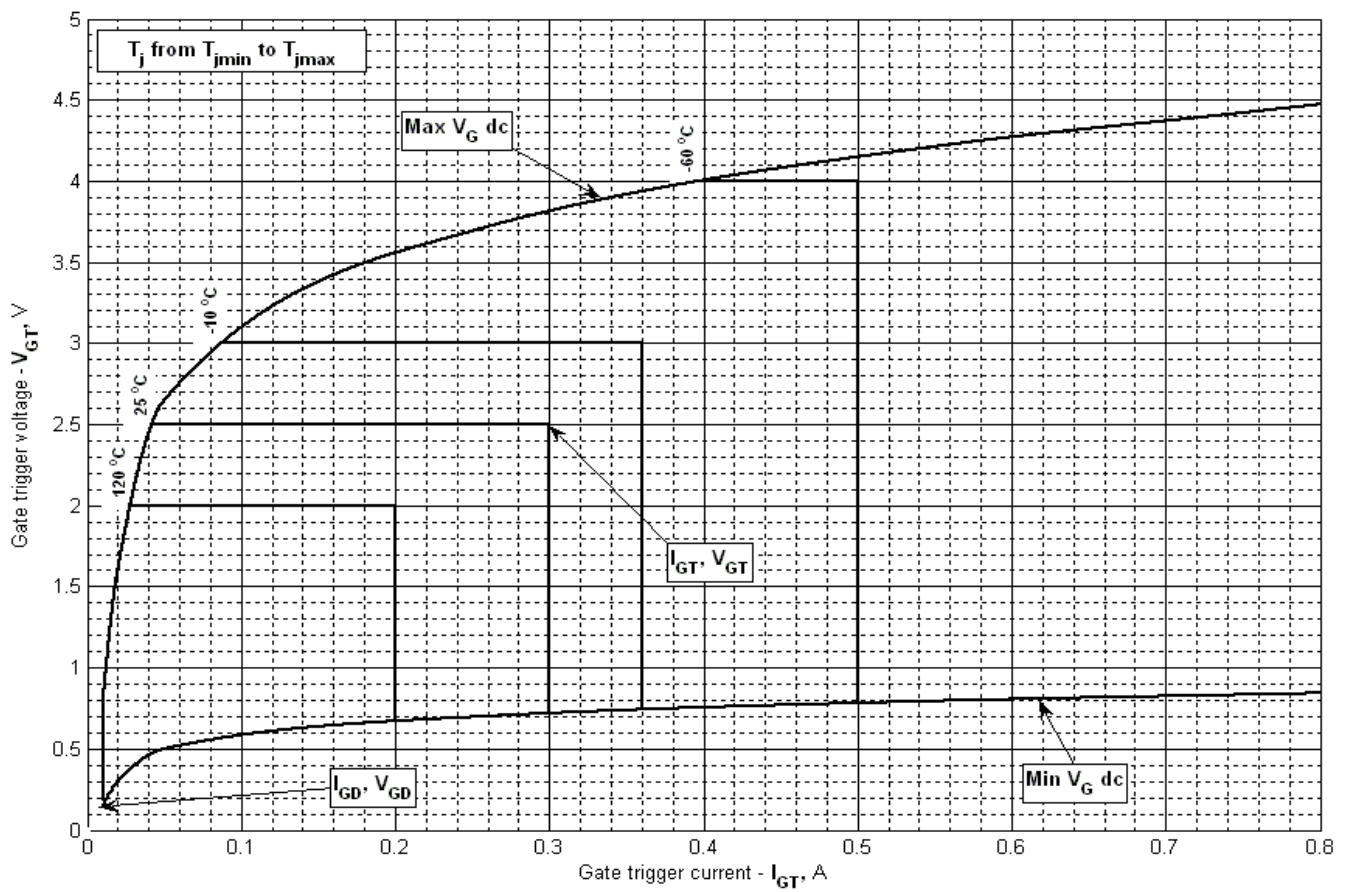


Fig 3 – Gate characteristics – Trigger limits

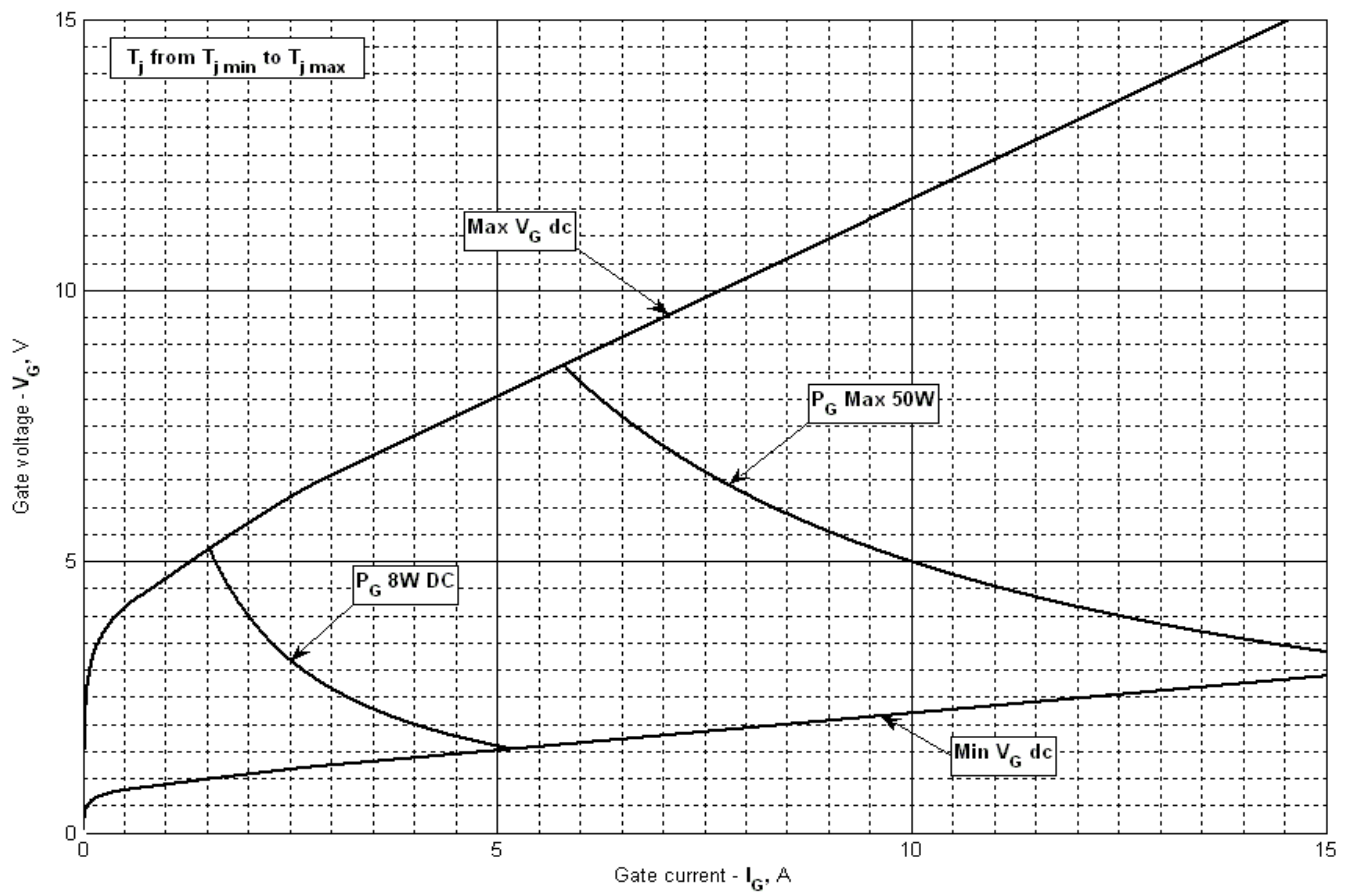


Fig 4 - Gate characteristics – Power curves

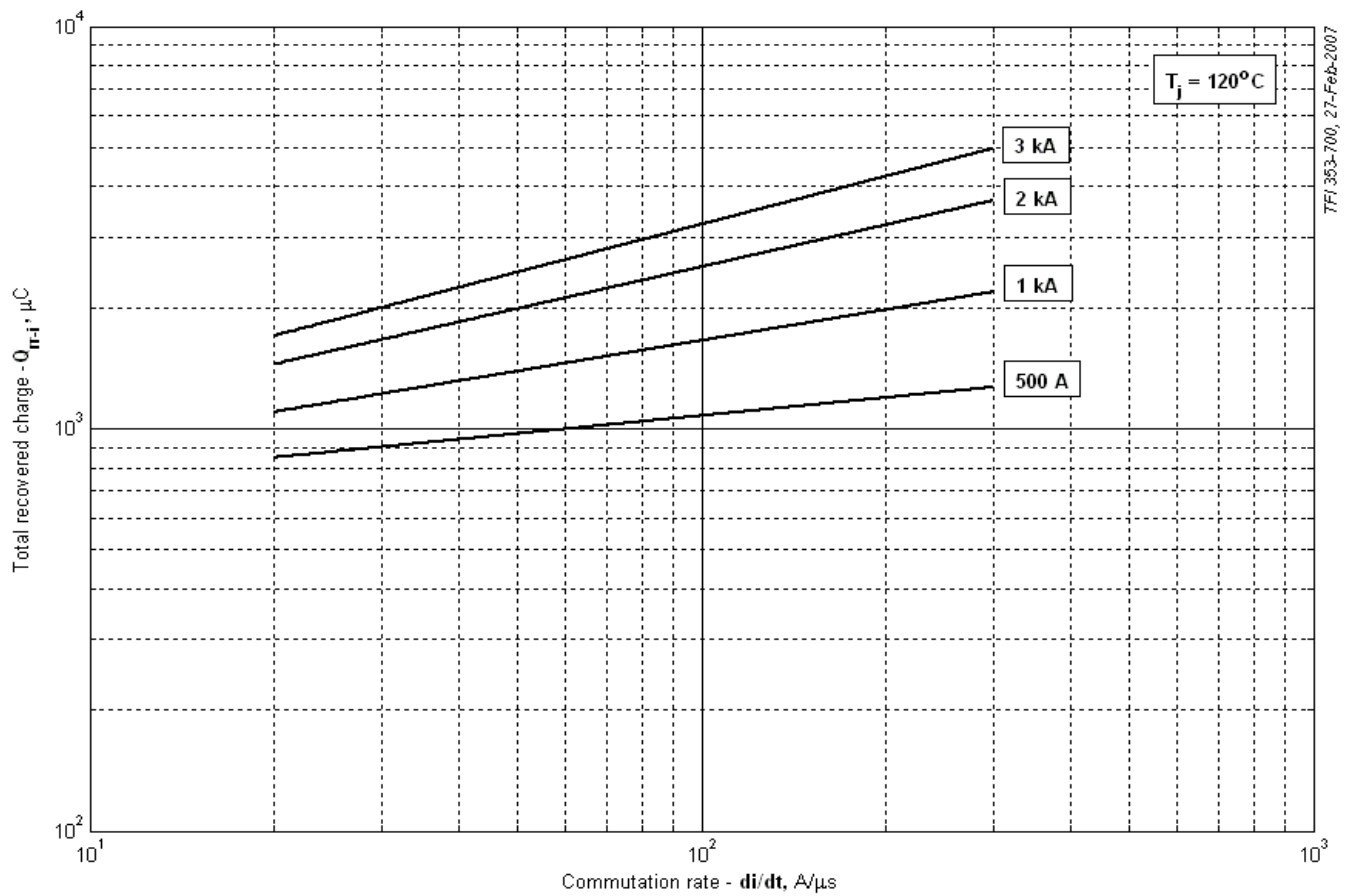


Fig 5 - Total recovered charge, Q_{rr-i} (integral)

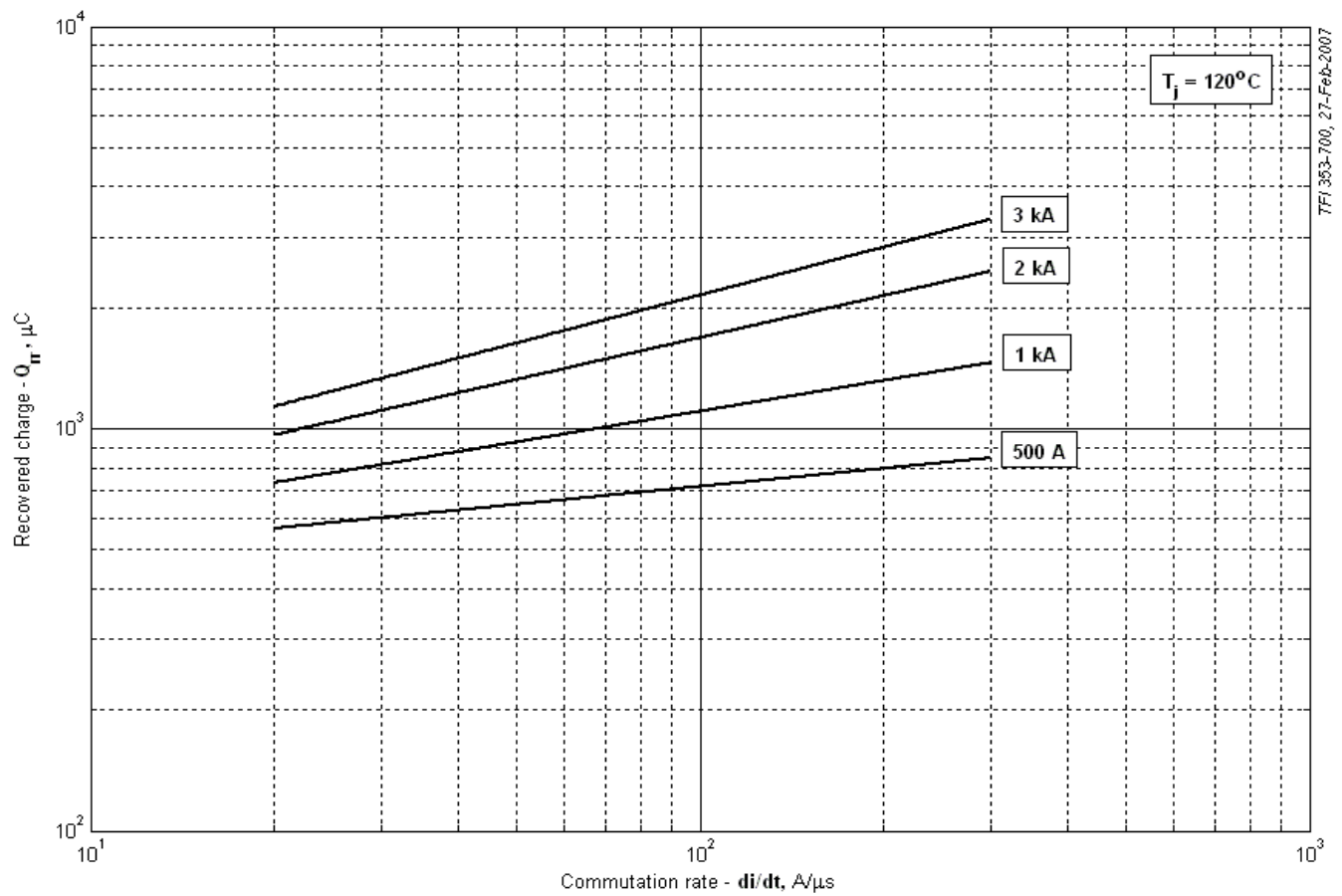


Fig 6 - Recovered charge, Q_{rr} (25% chord)

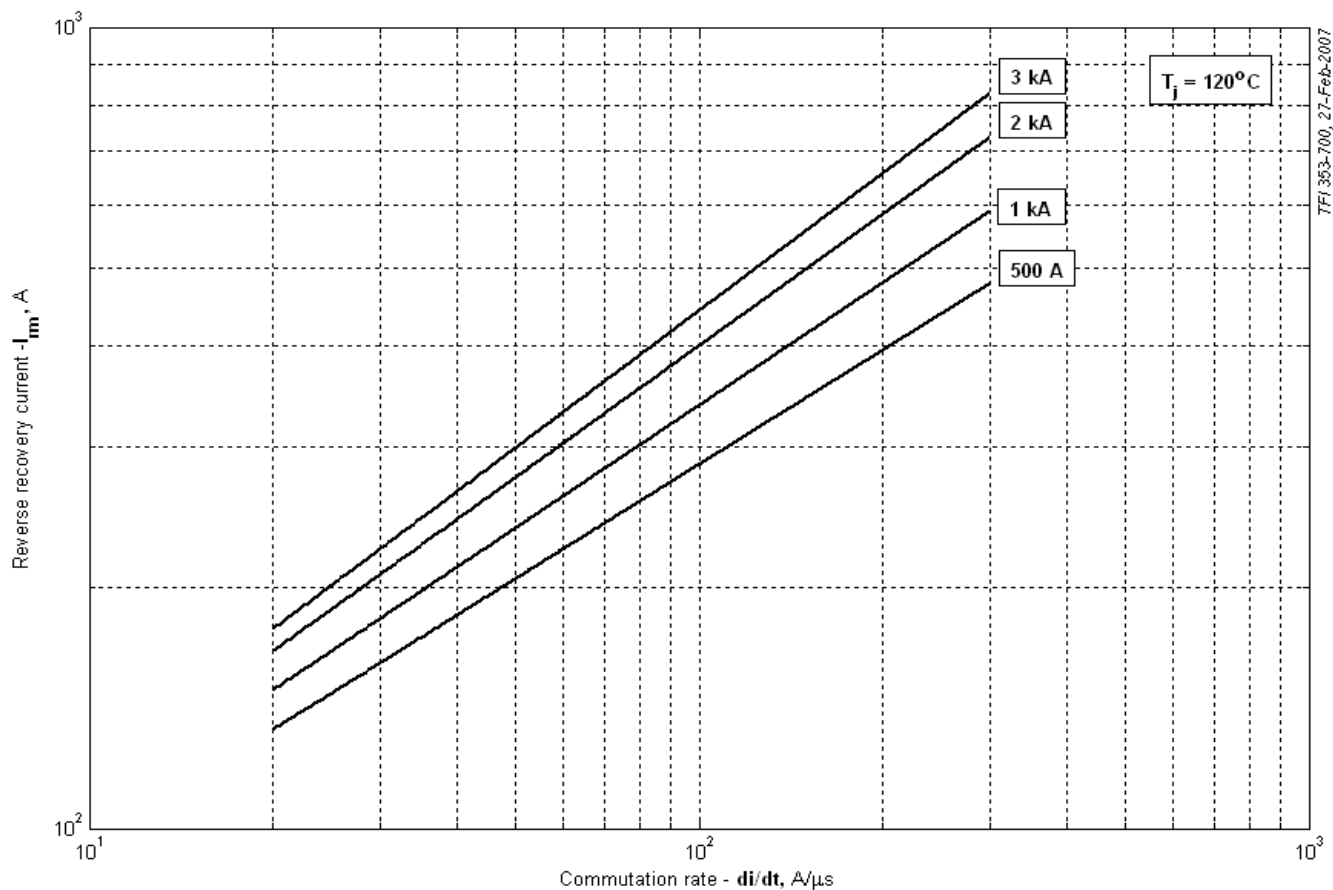


Fig 7 - Peak reverse recovery current, I_{rr}

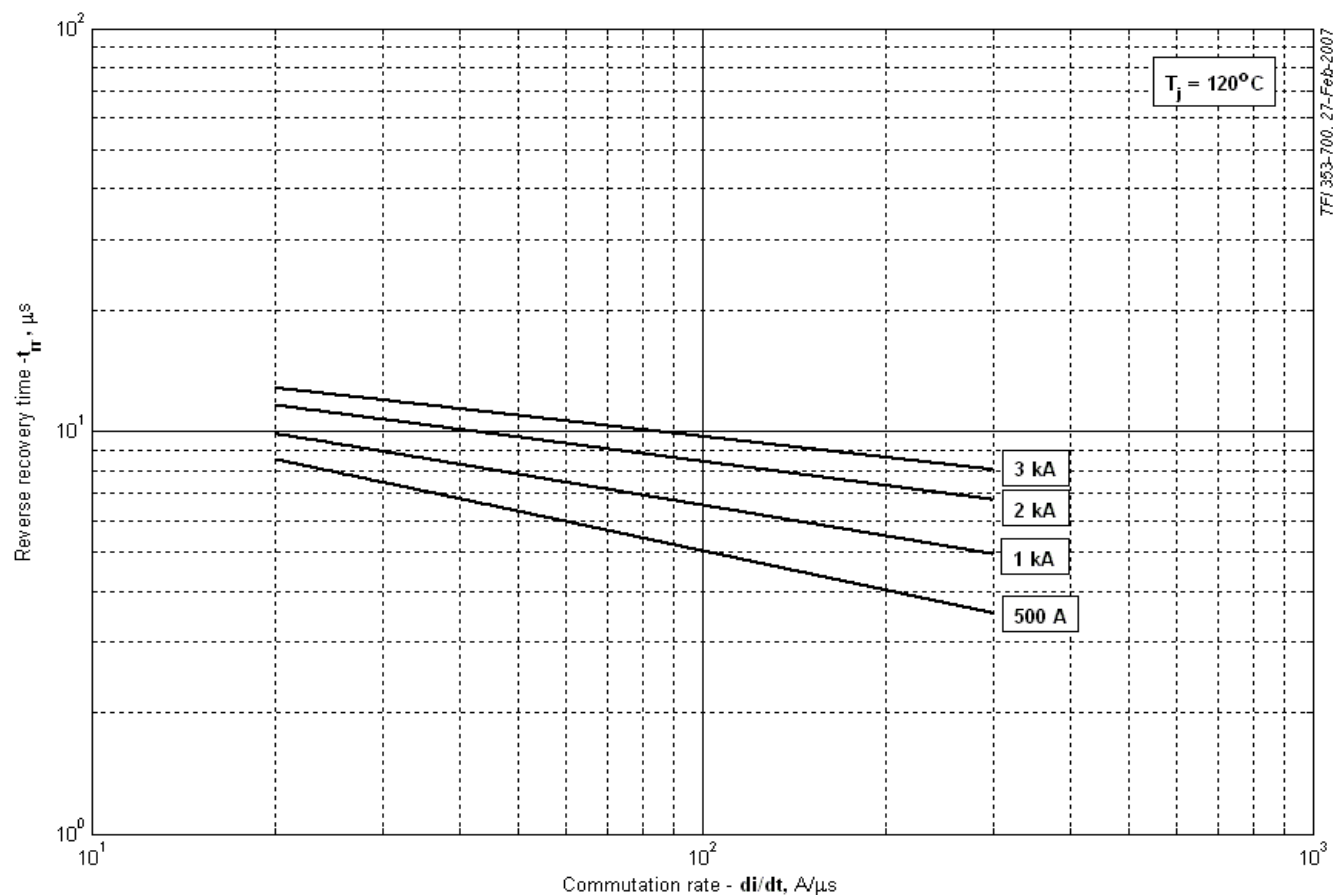


Fig 8 - Maximum recovery time, t_r (25% chord)

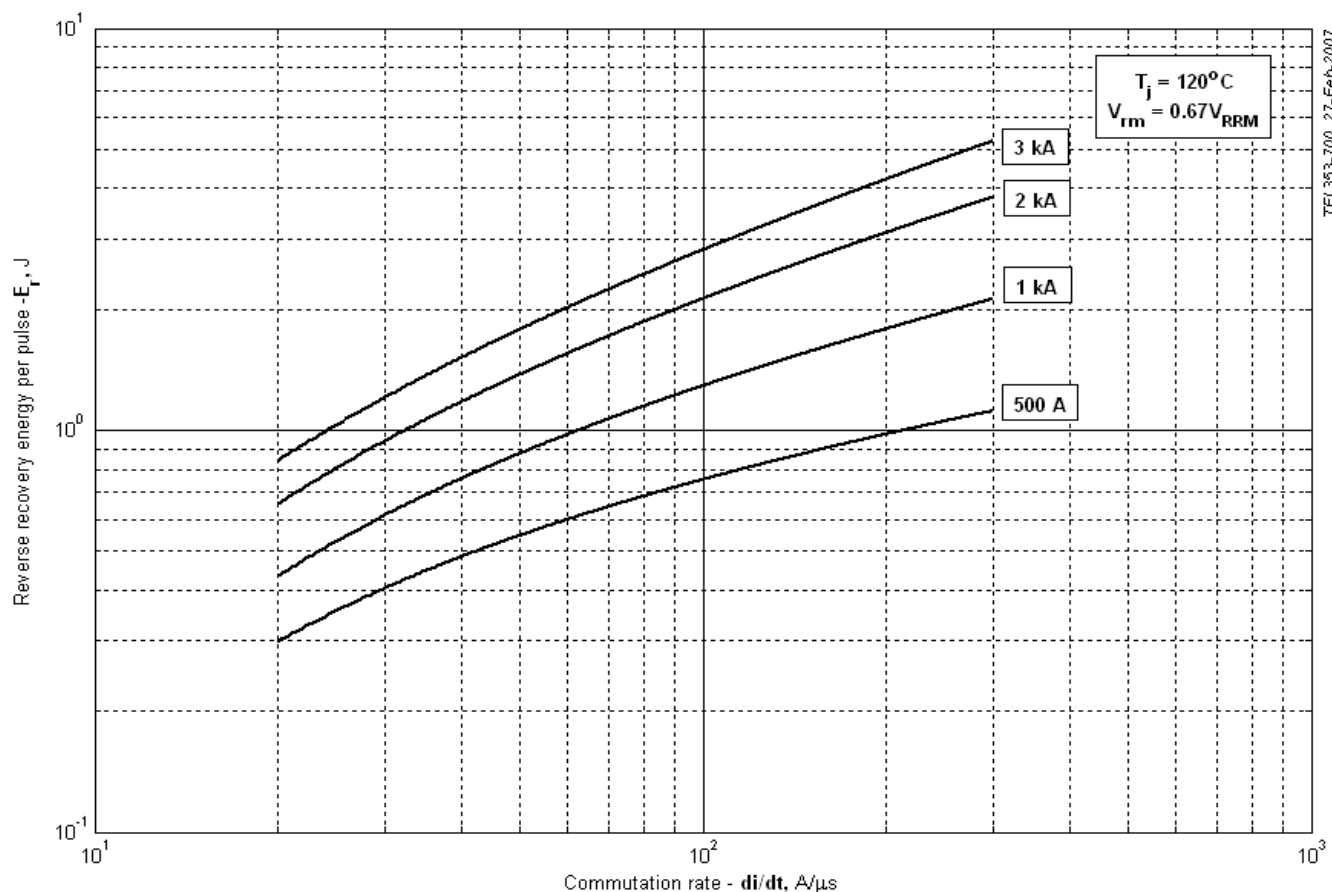


Fig 9 – Reverse recovery energy per pulse

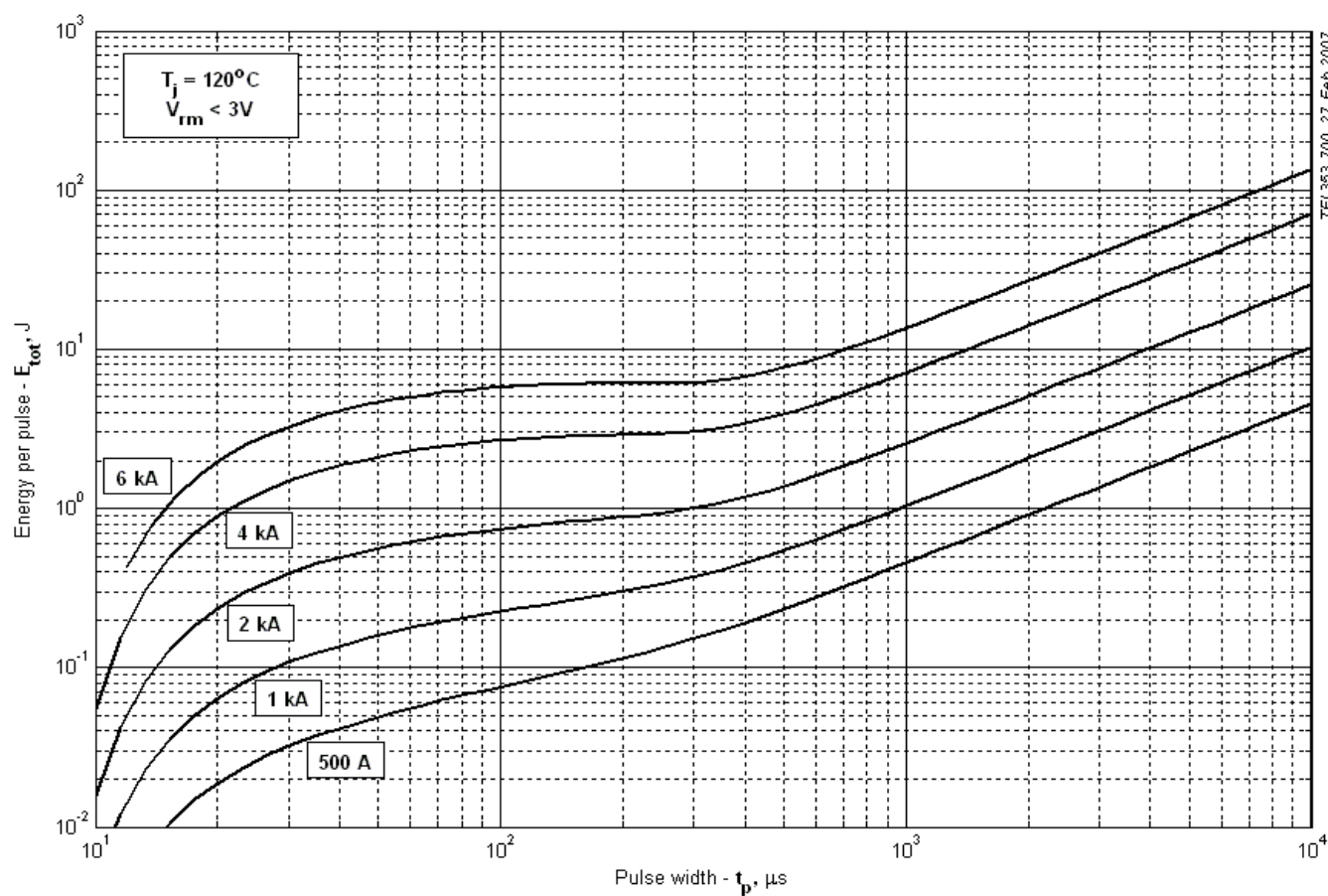


Fig 10 – Sine wave energy per pulse

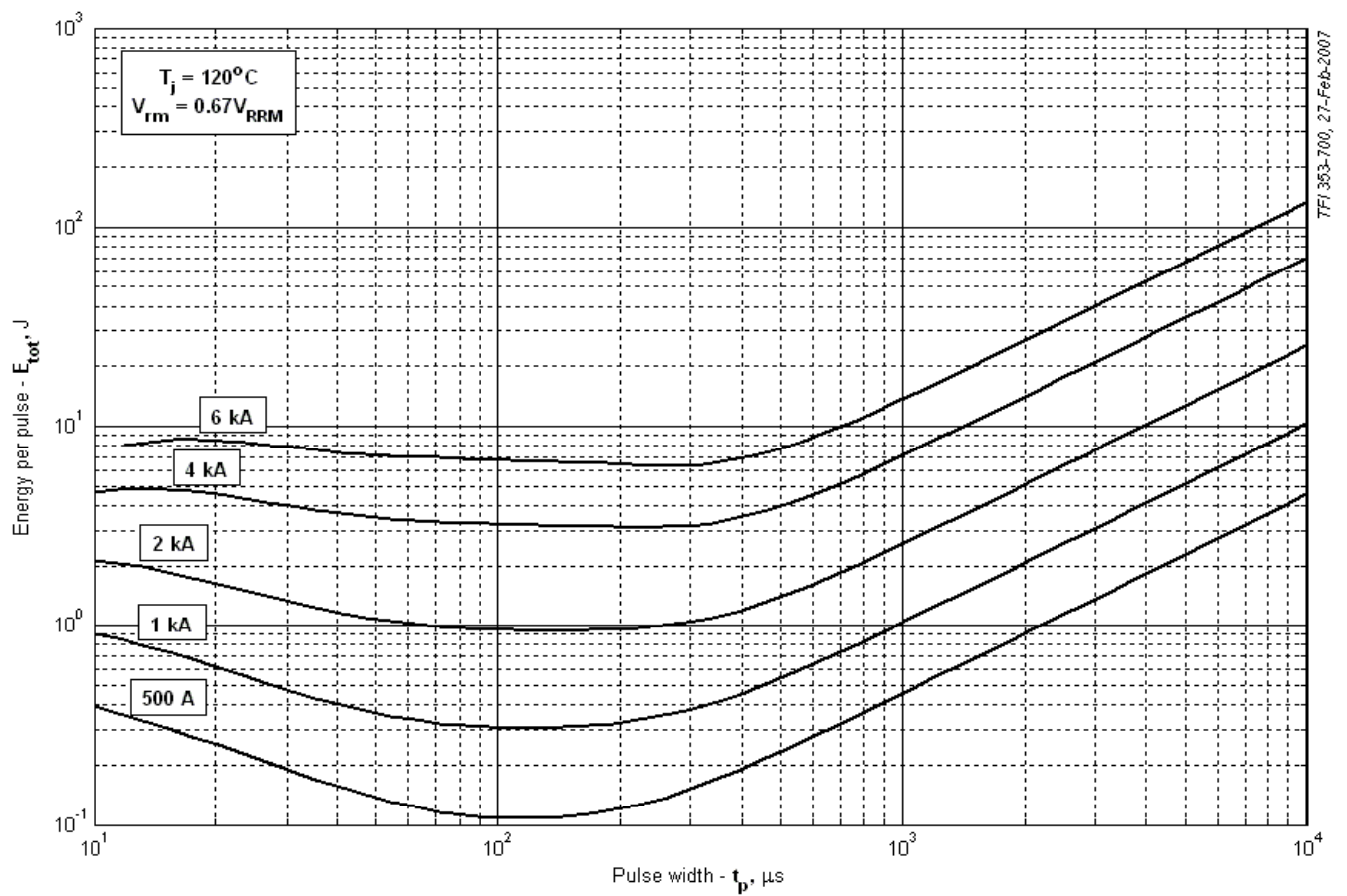


Fig 11 – Sine wave energy per pulse

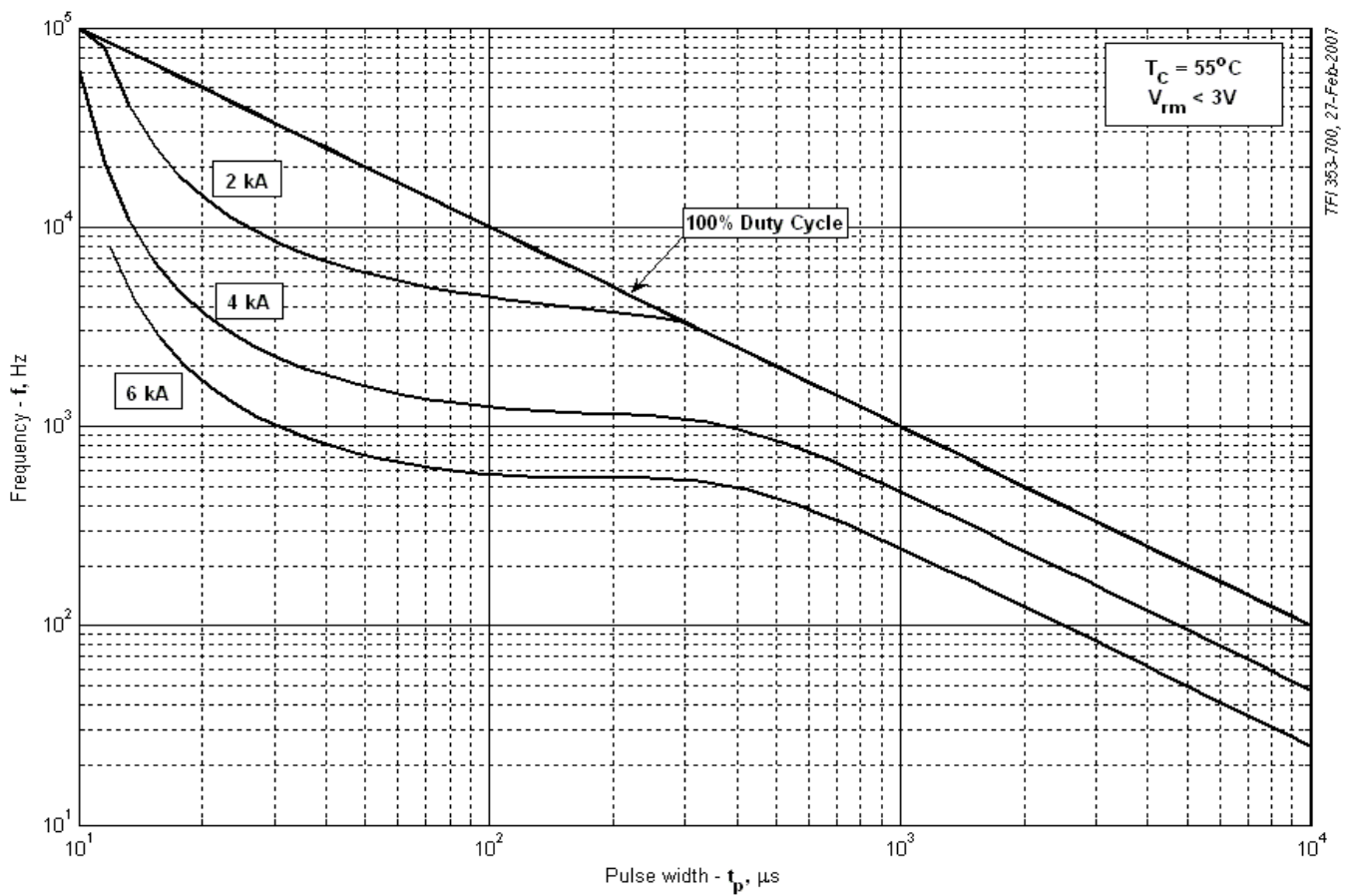


Fig 12 – Sine wave frequency ratings

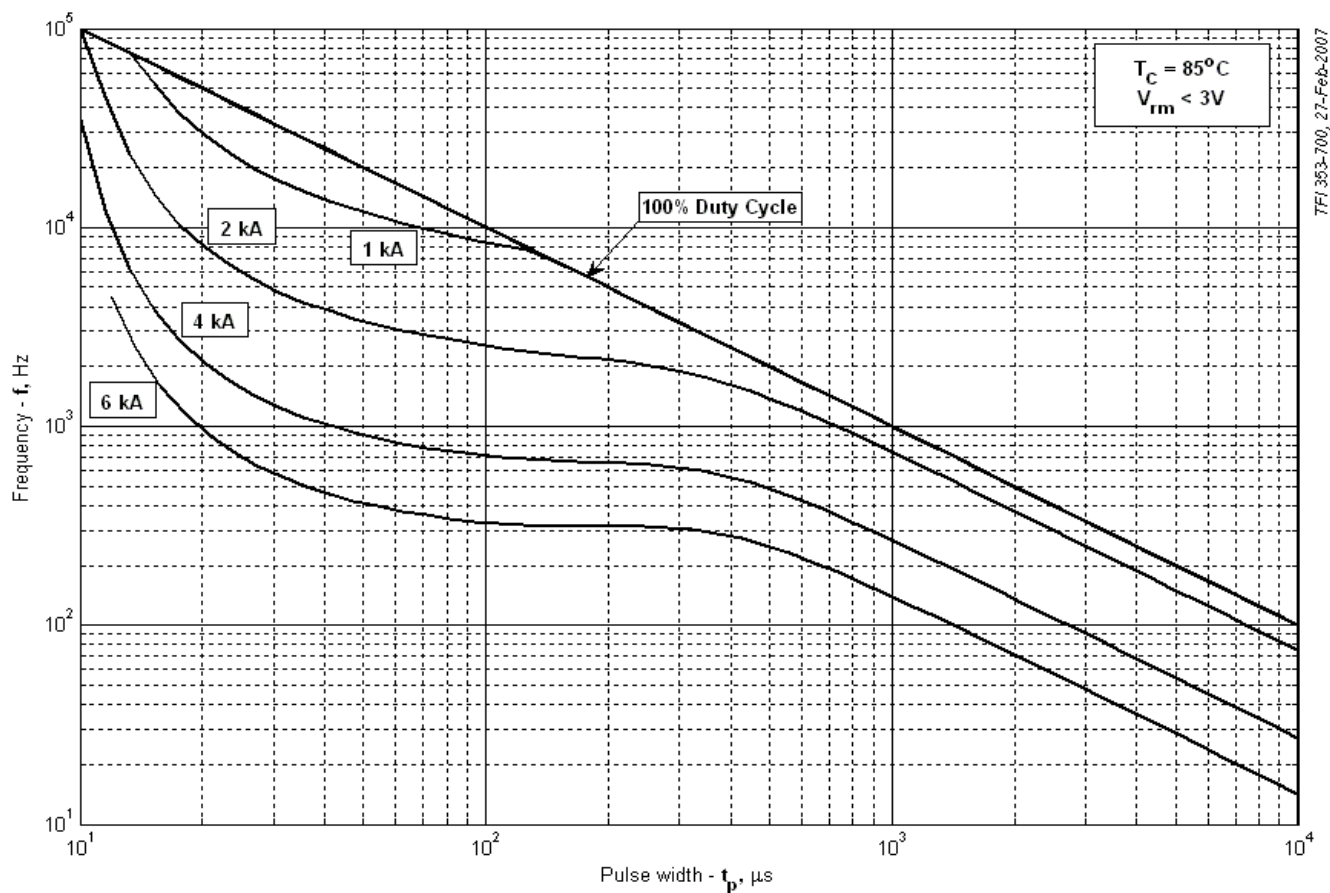


Fig 13 – Sine wave frequency ratings

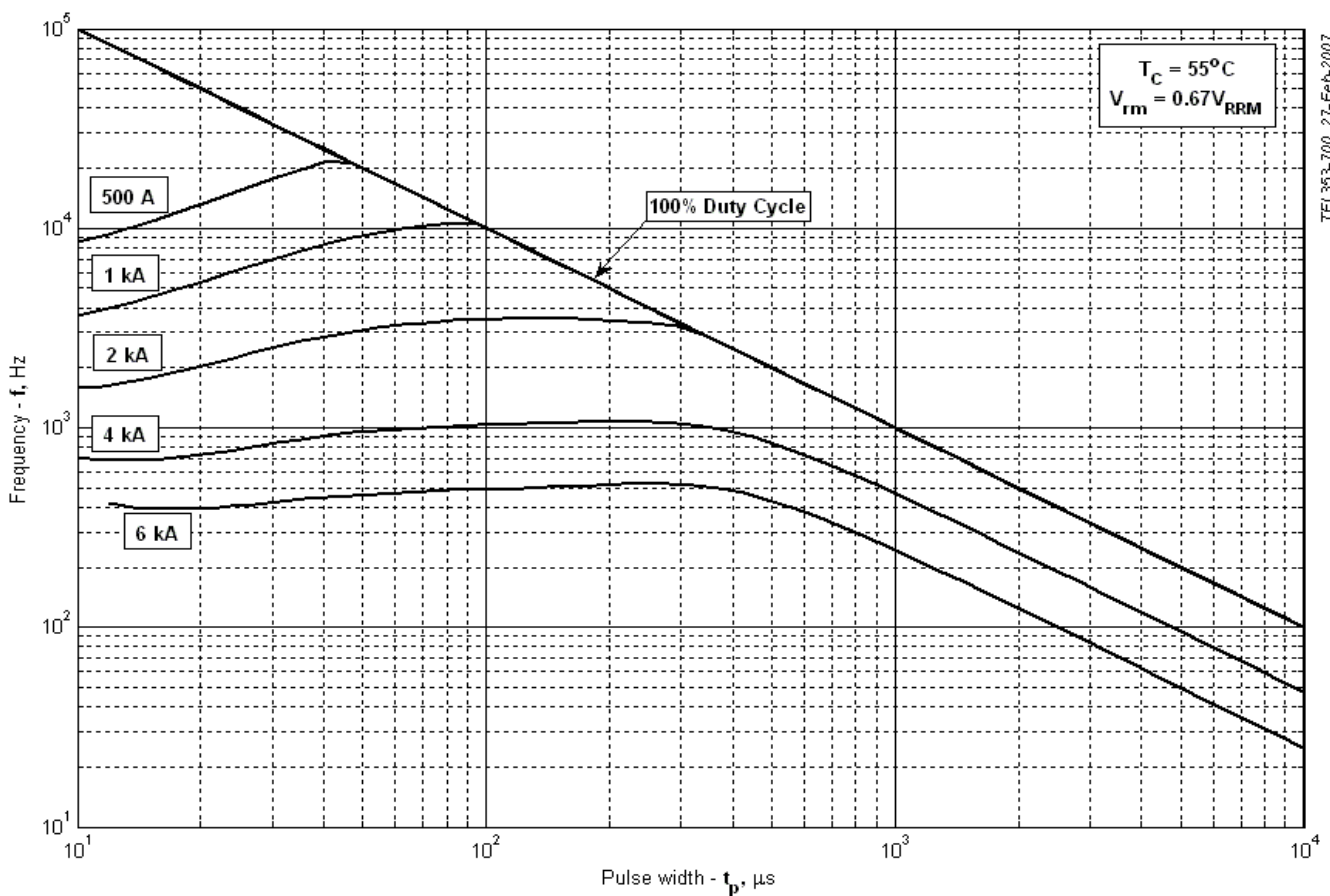


Fig 14 – Sine wave frequency ratings

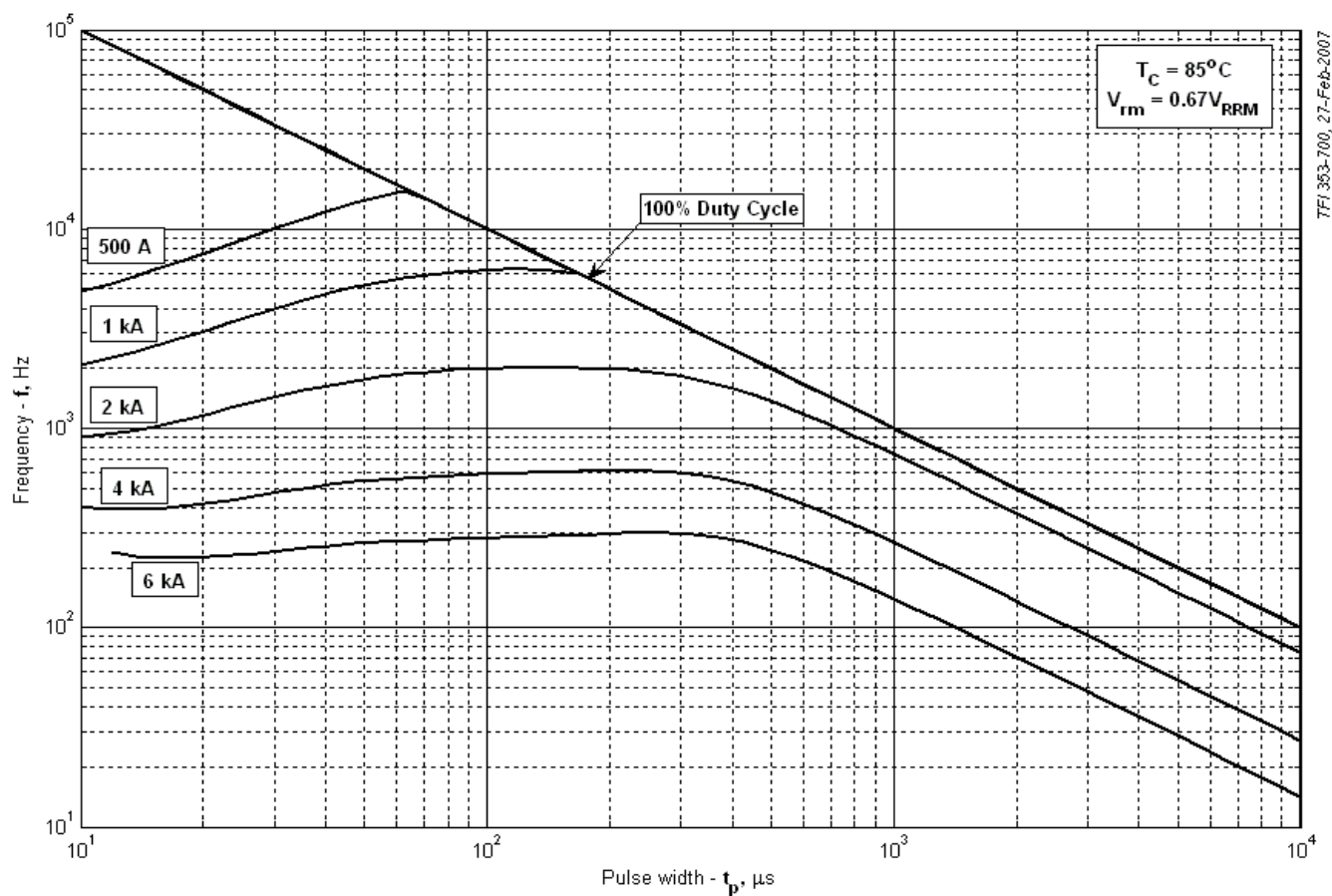


Fig 15 – Sine wave frequency ratings

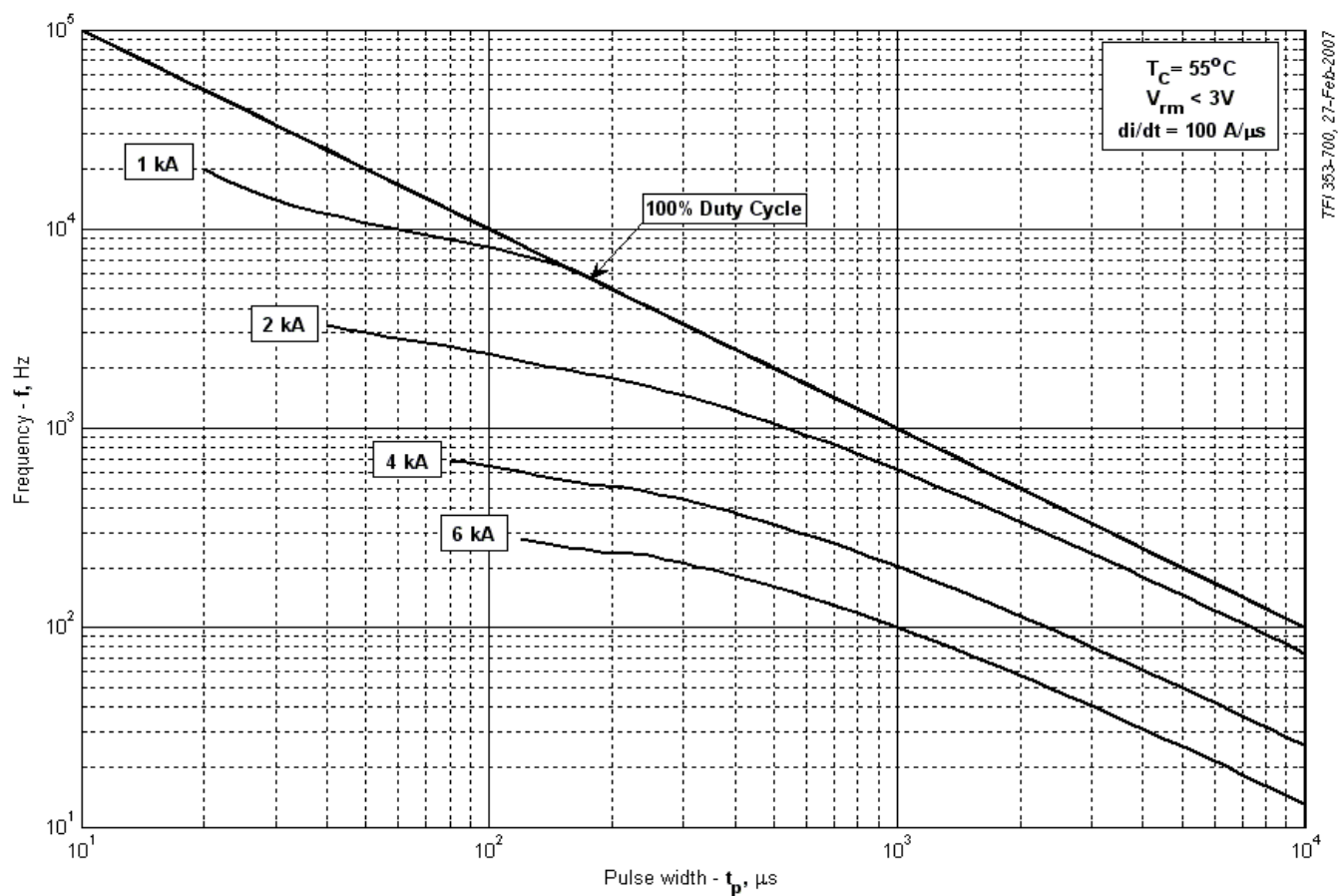


Fig 16 – Square wave frequency ratings

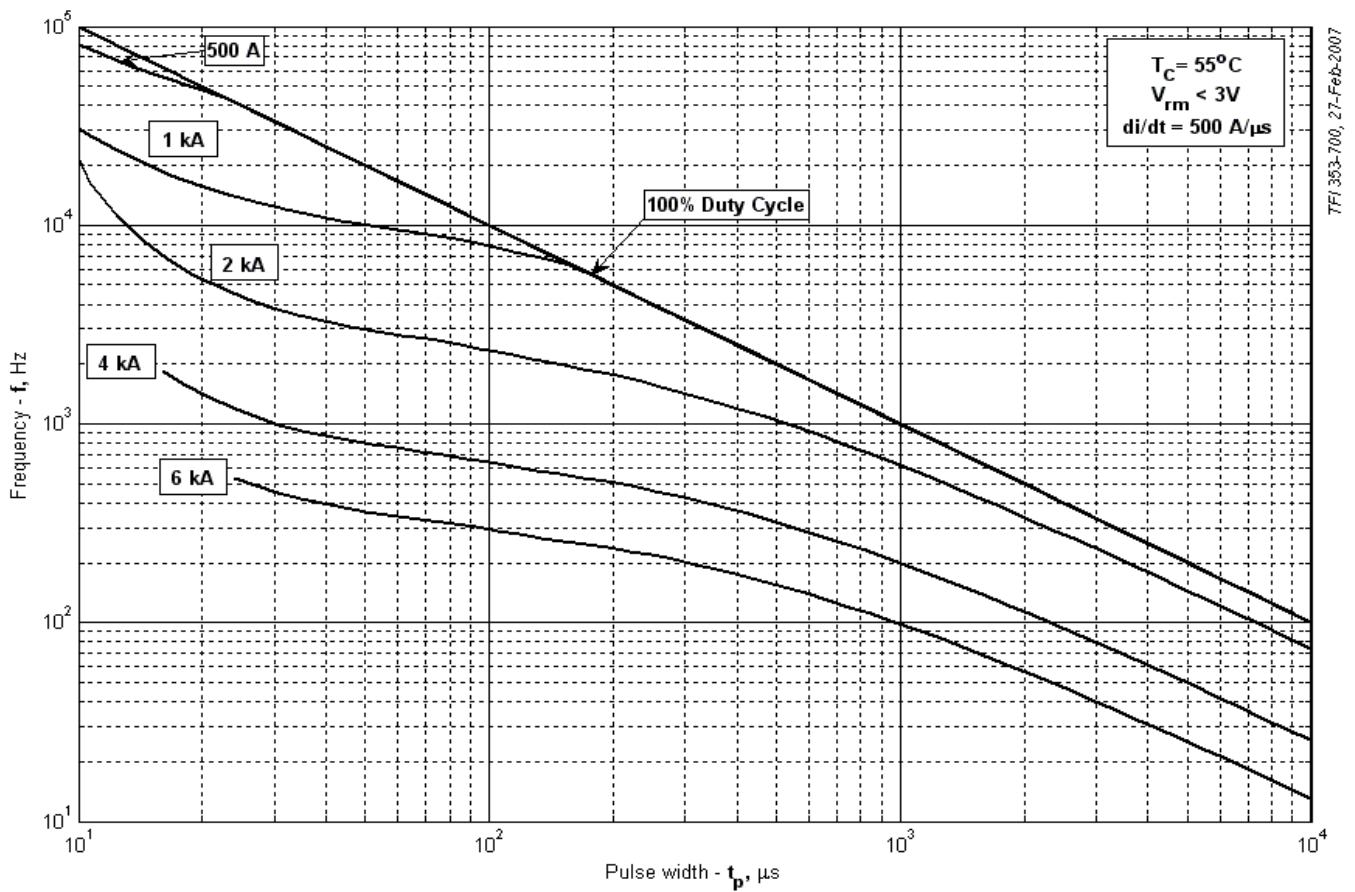


Fig 17 – Square wave frequency ratings

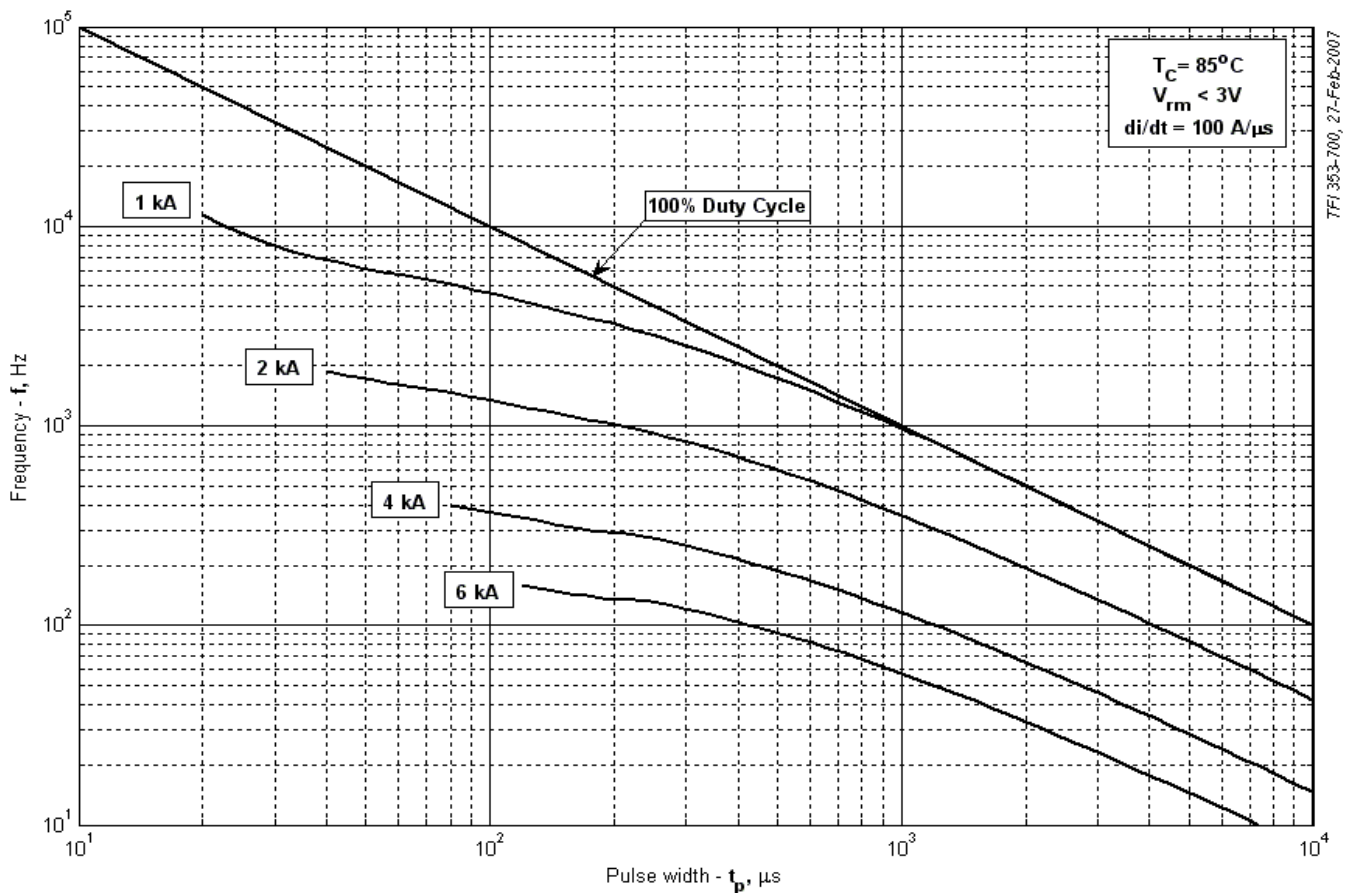


Fig 18 – Square wave frequency ratings

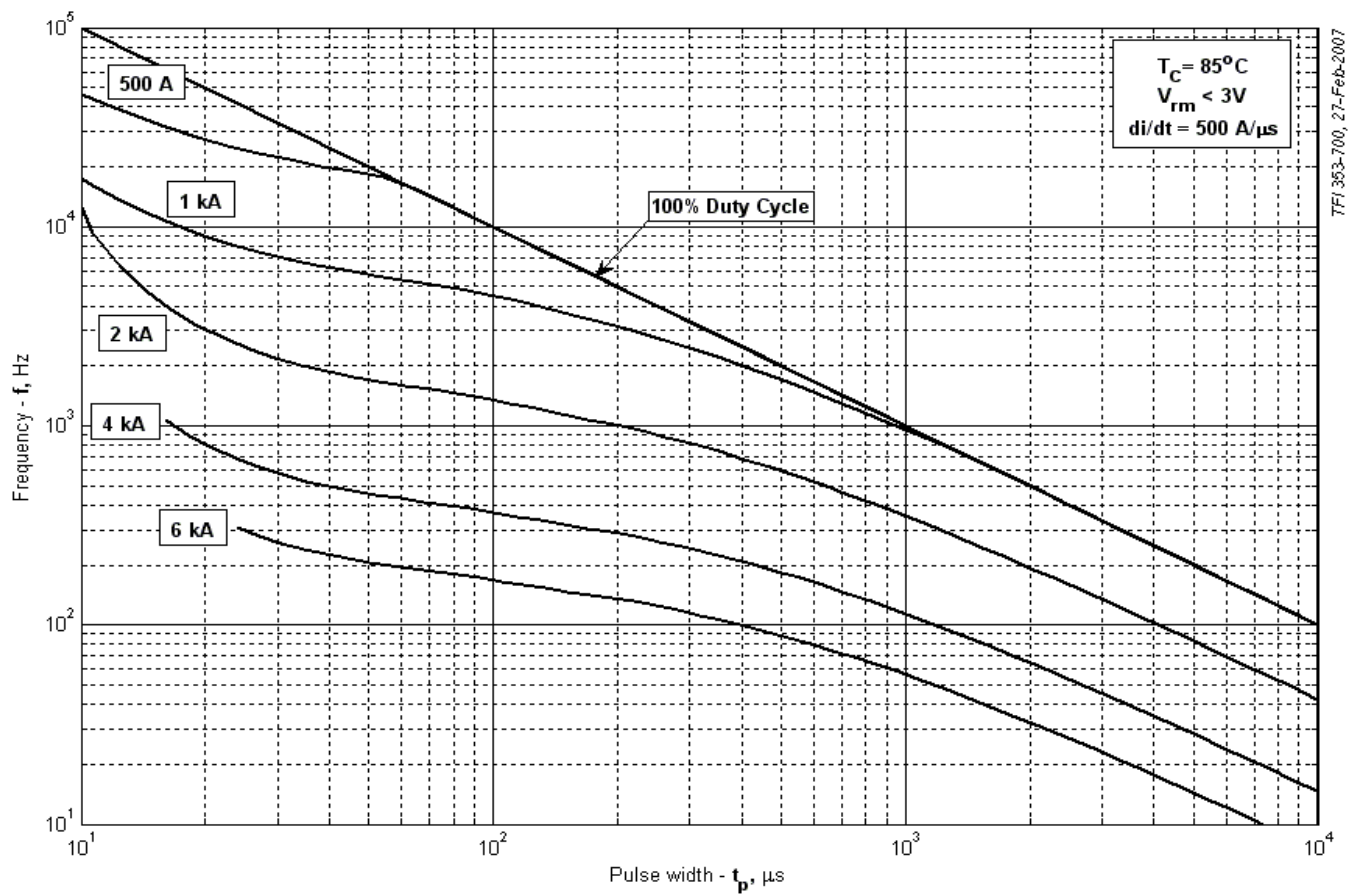


Fig 19 – Square wave frequency ratings

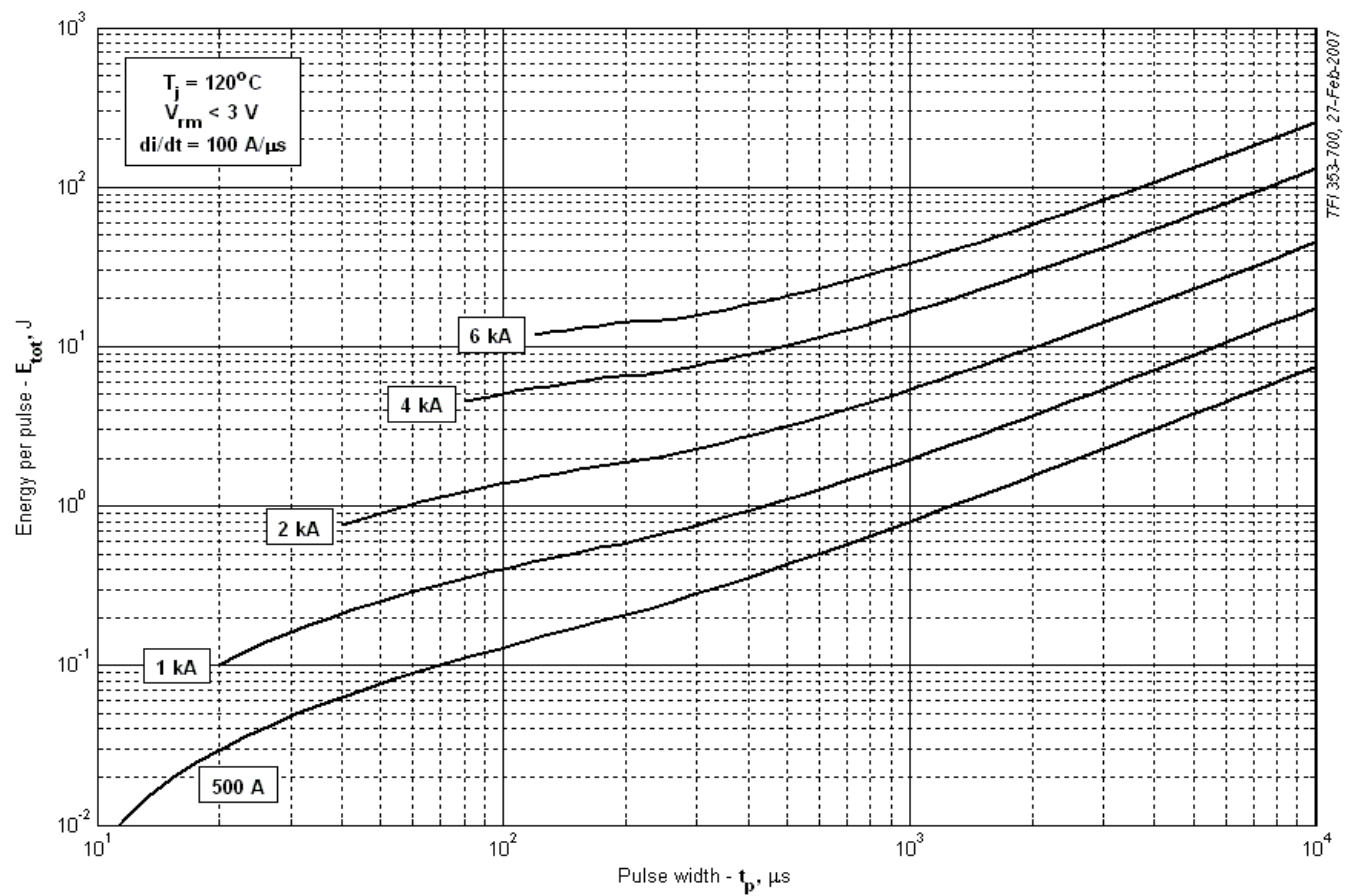


Fig 20 – Square wave energy per pulse

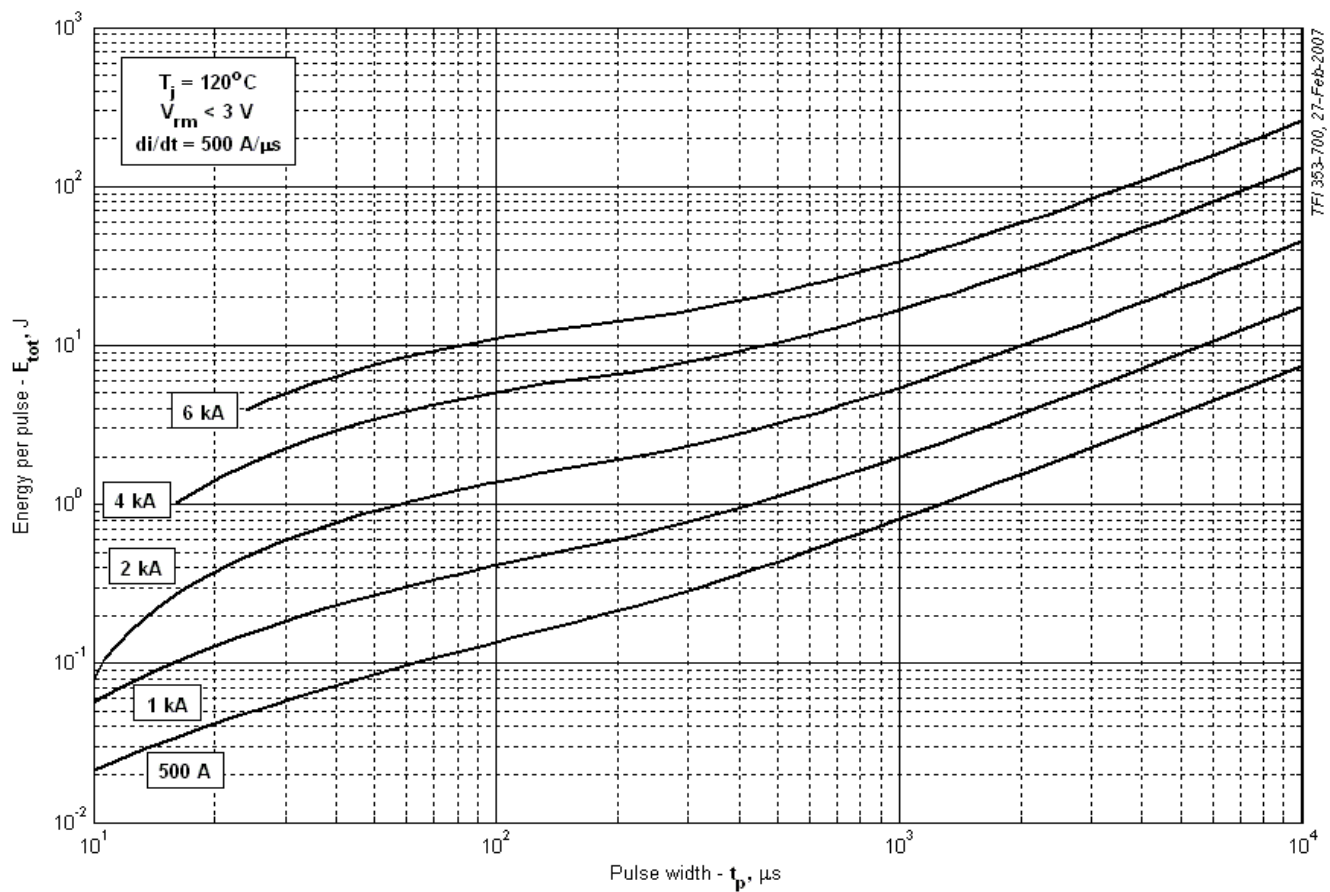


Fig 21 – Square wave energy per pulse

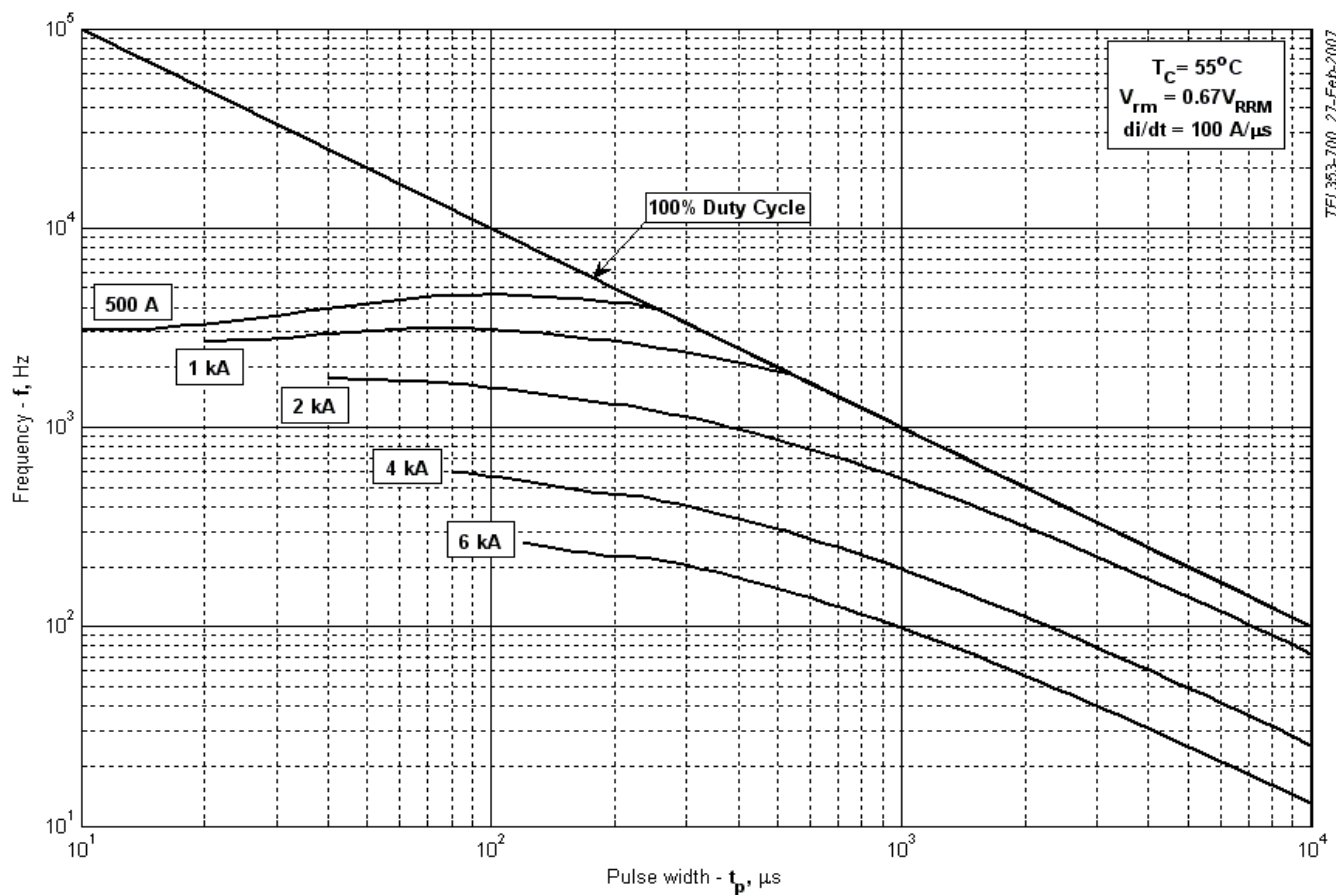


Fig 22 – Square wave frequency ratings

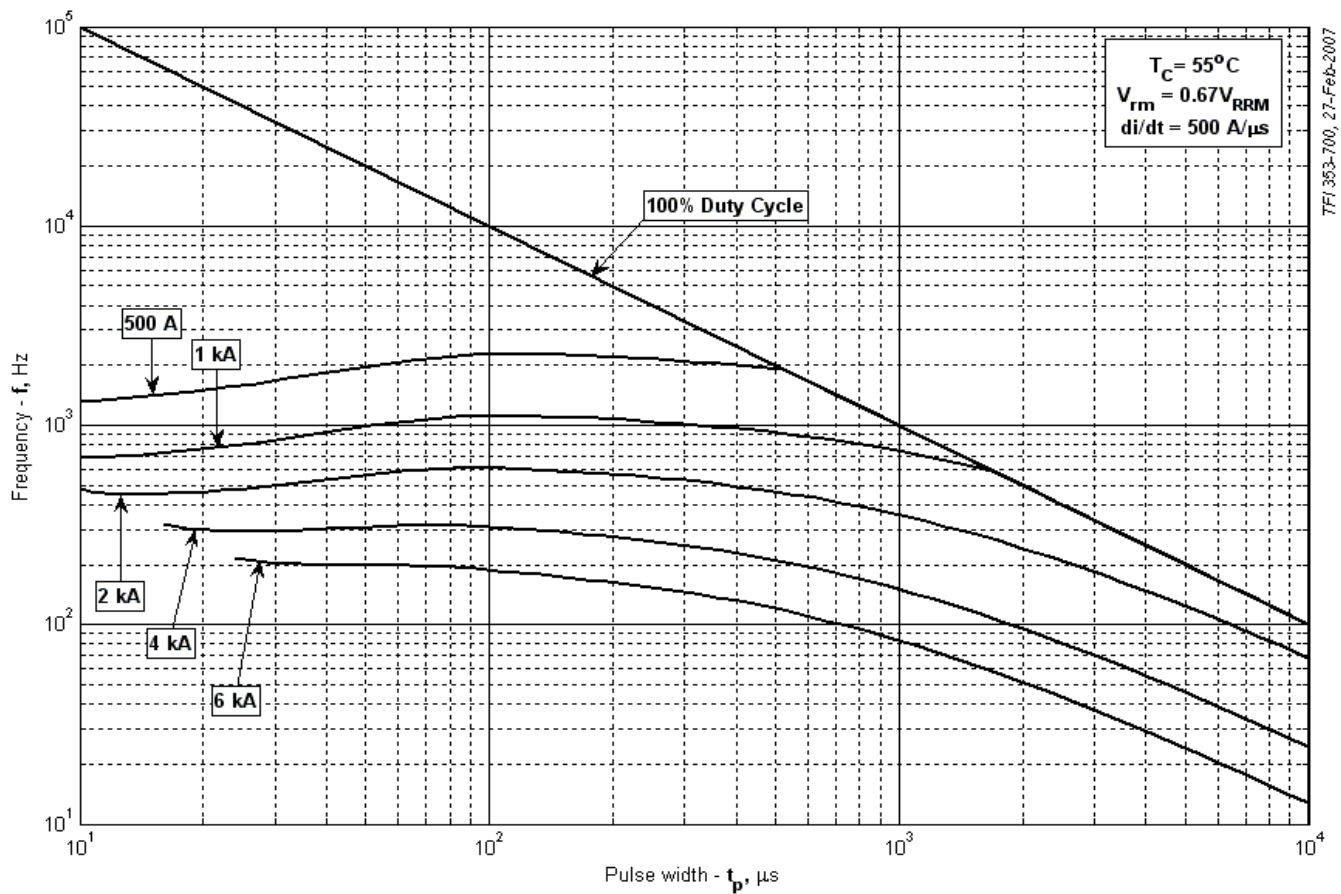


Fig 23 – Square wave frequency ratings

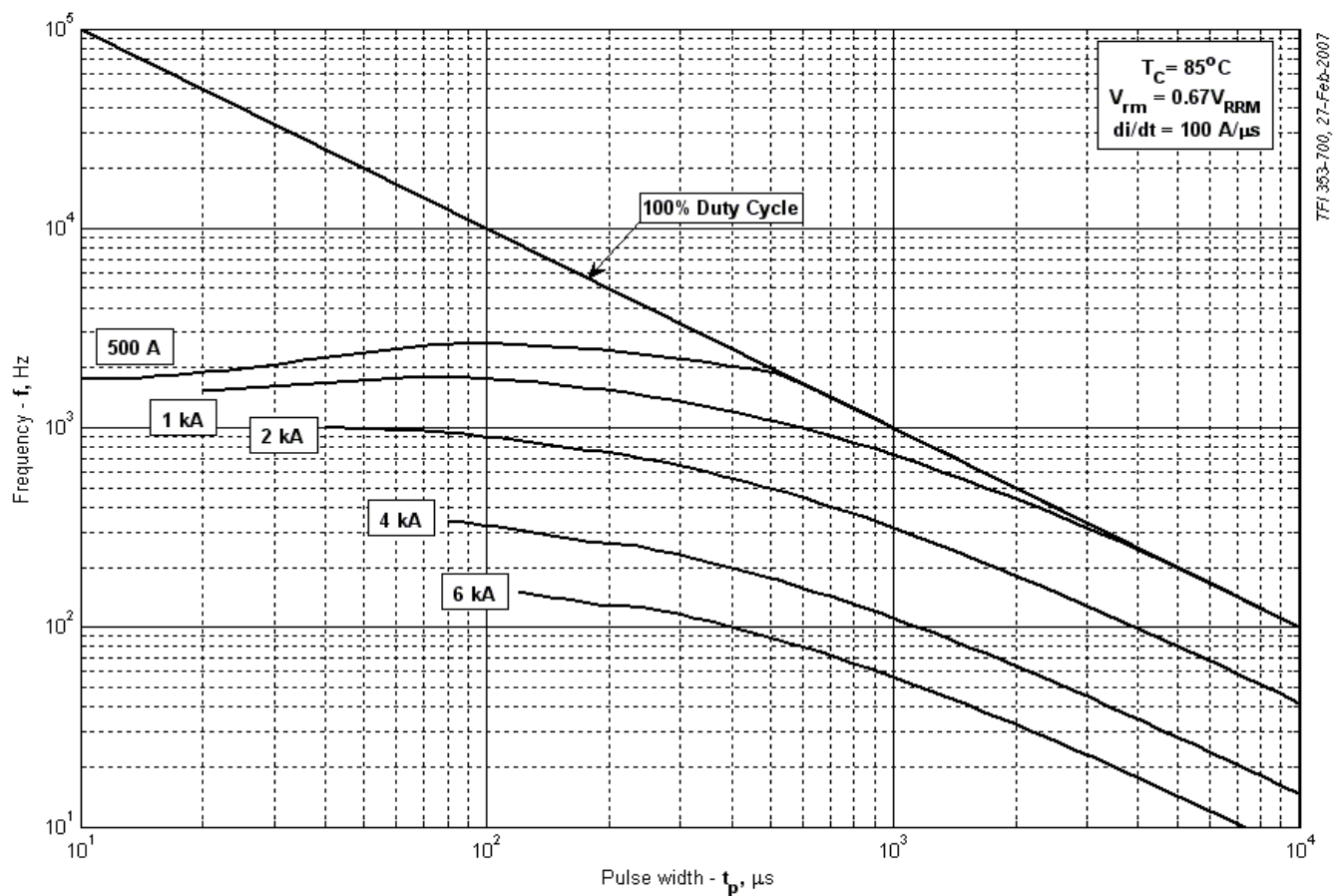


Fig 24 – Square wave frequency ratings

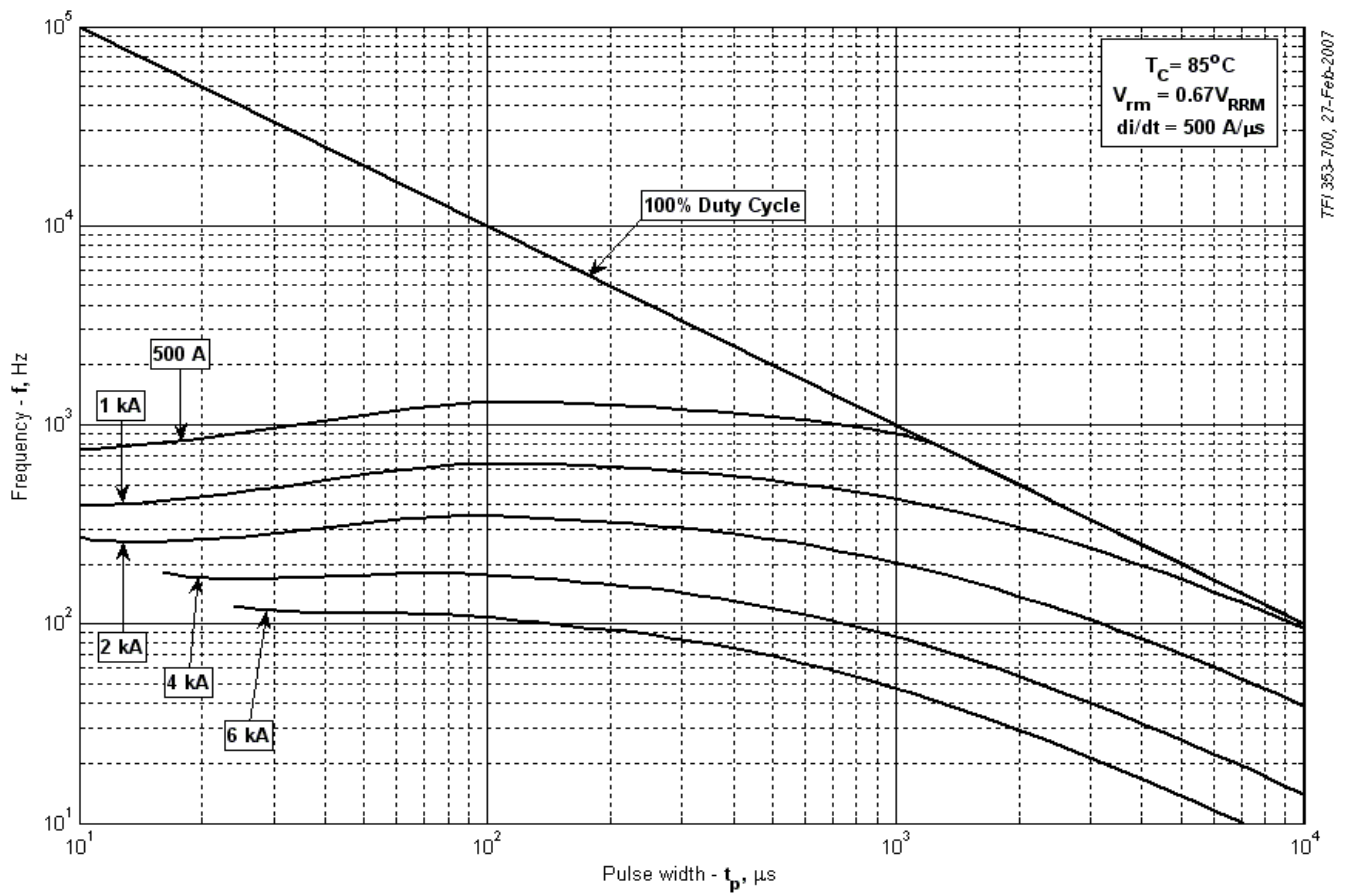


Fig 25 – Square wave frequency ratings

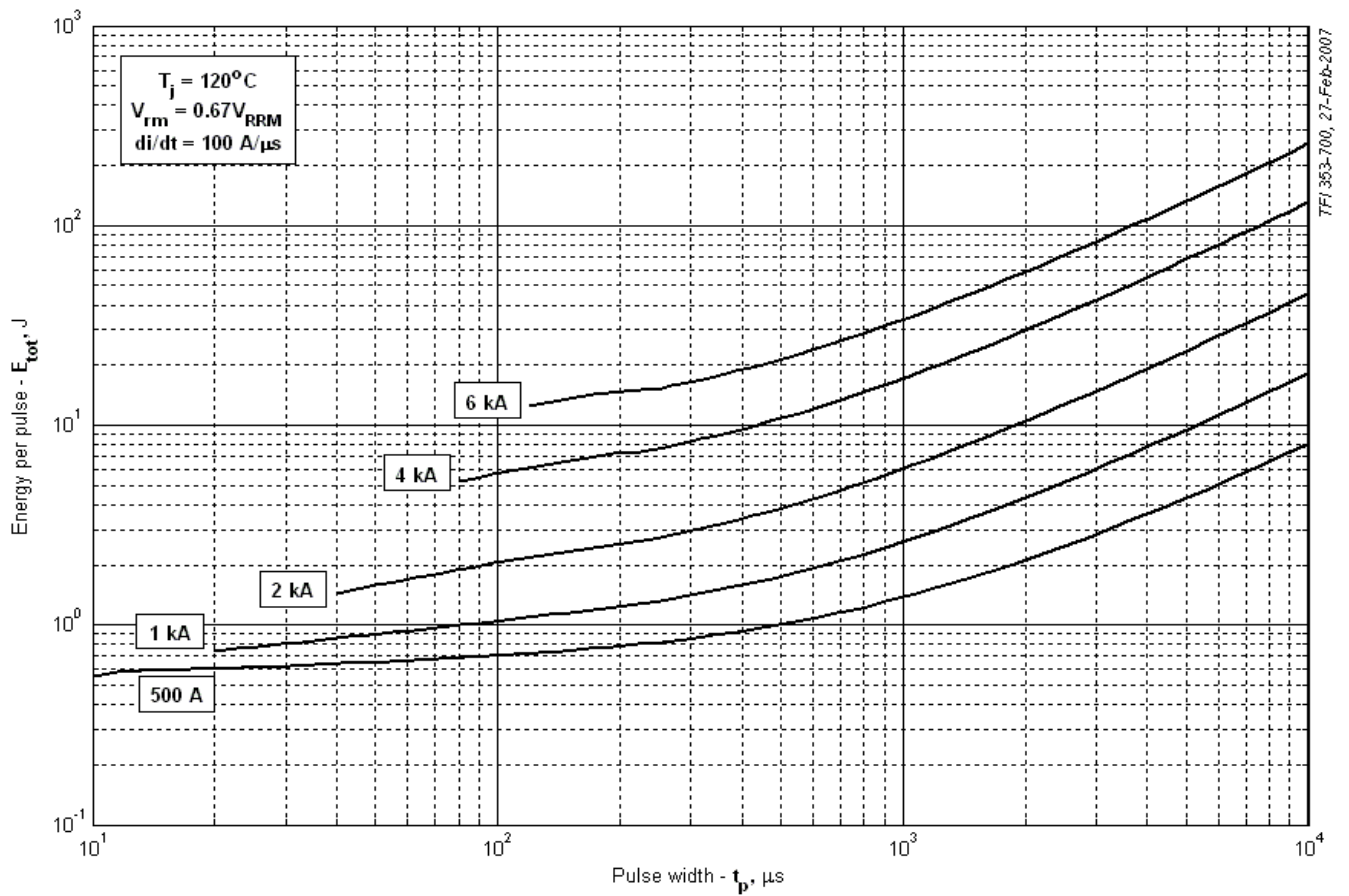


Fig 26 – Square wave energy per pulse

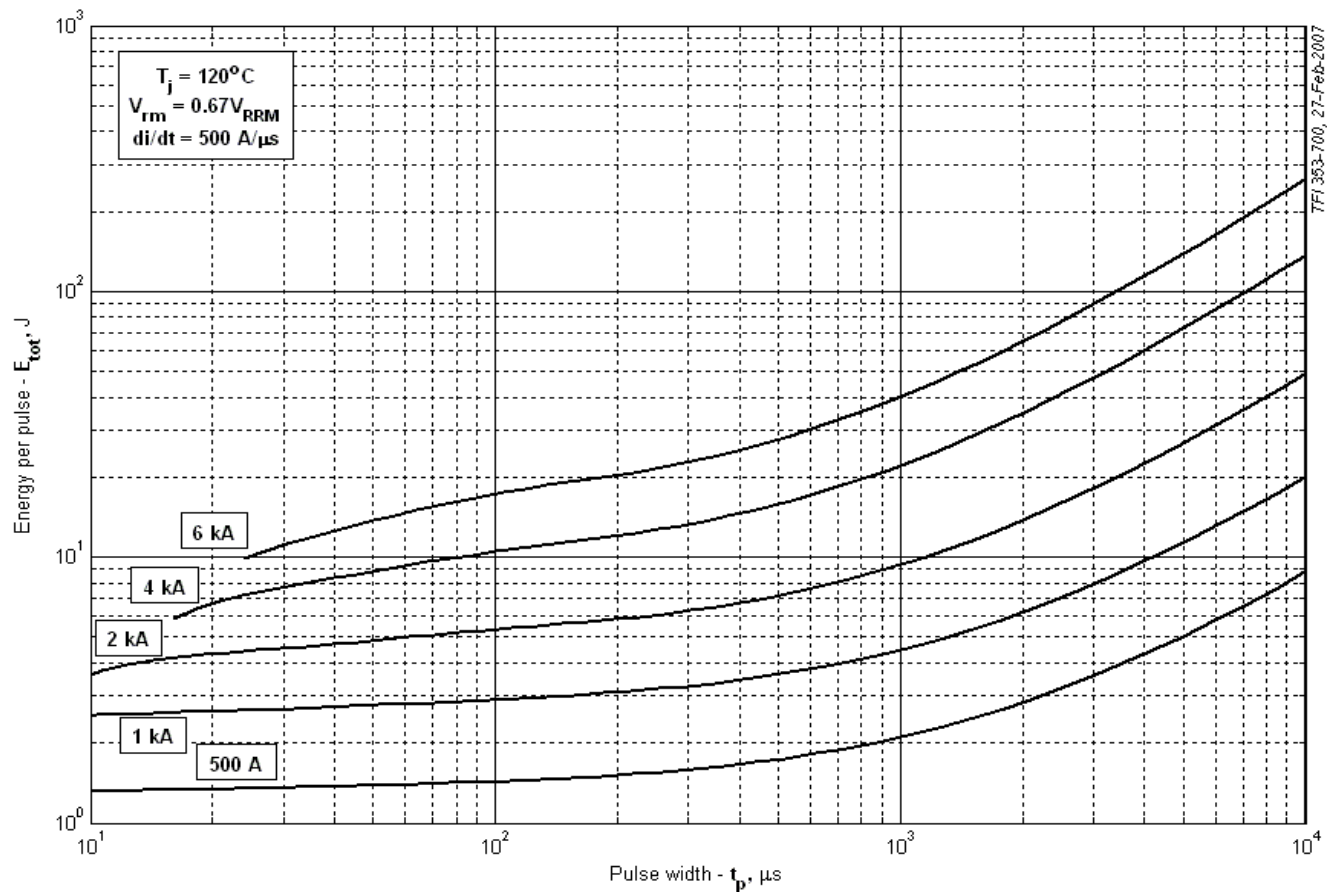


Fig 27 – Square wave energy per pulse

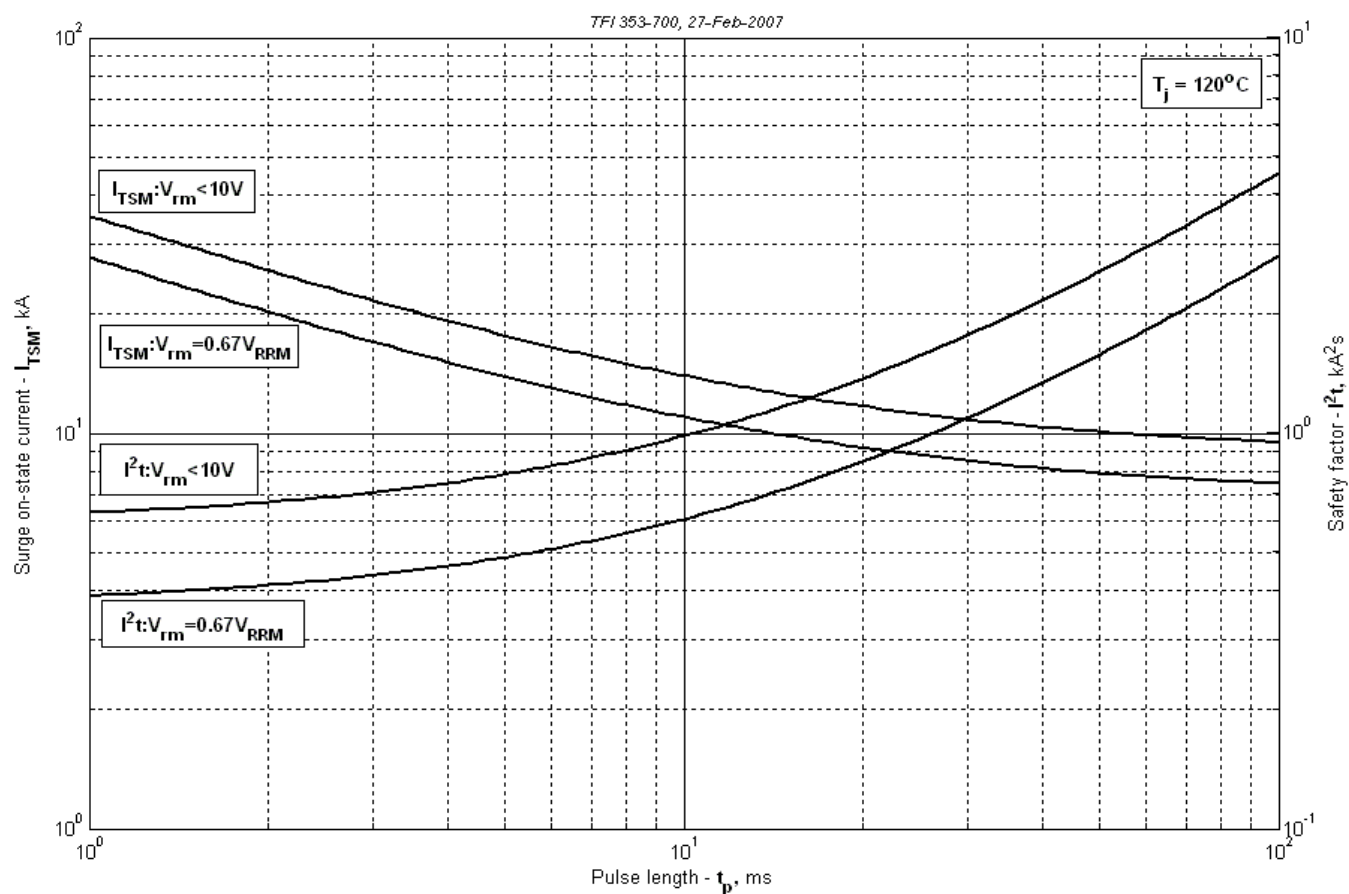


Fig 29 – Maximum surge and I^2t ratings

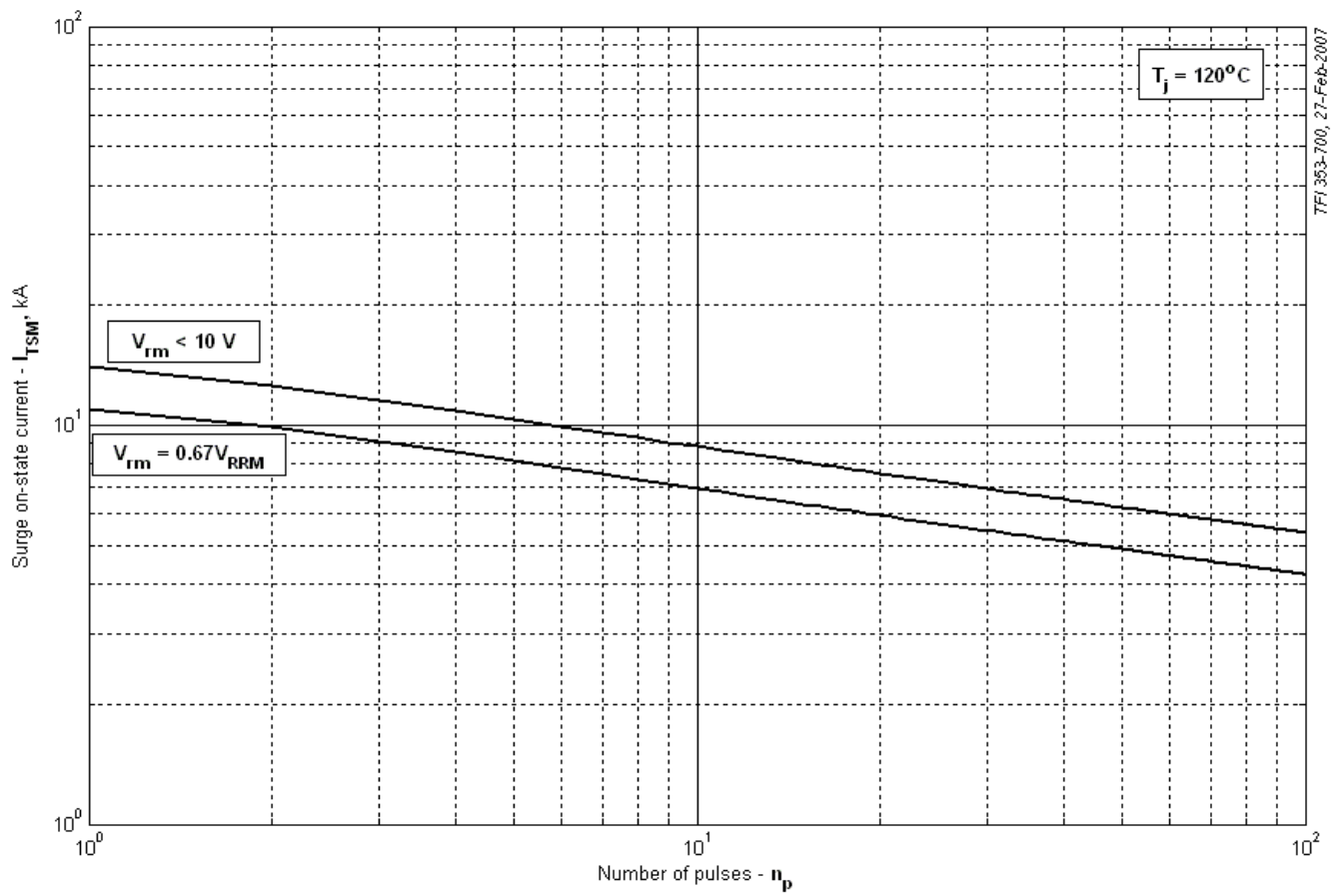


Fig 30 – Maximum surge ratings